



Preliminary Test Beam Results on 2nd BNL Production

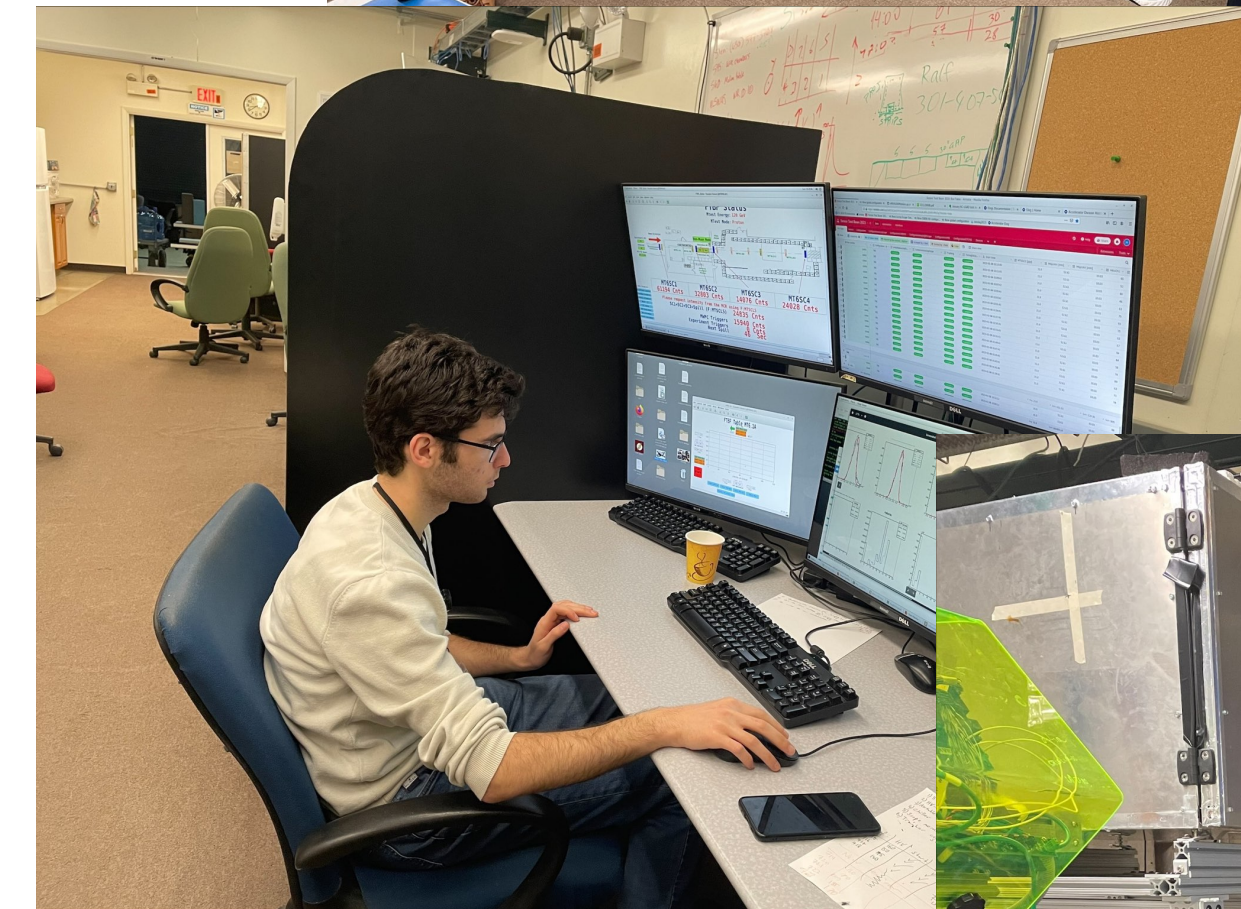
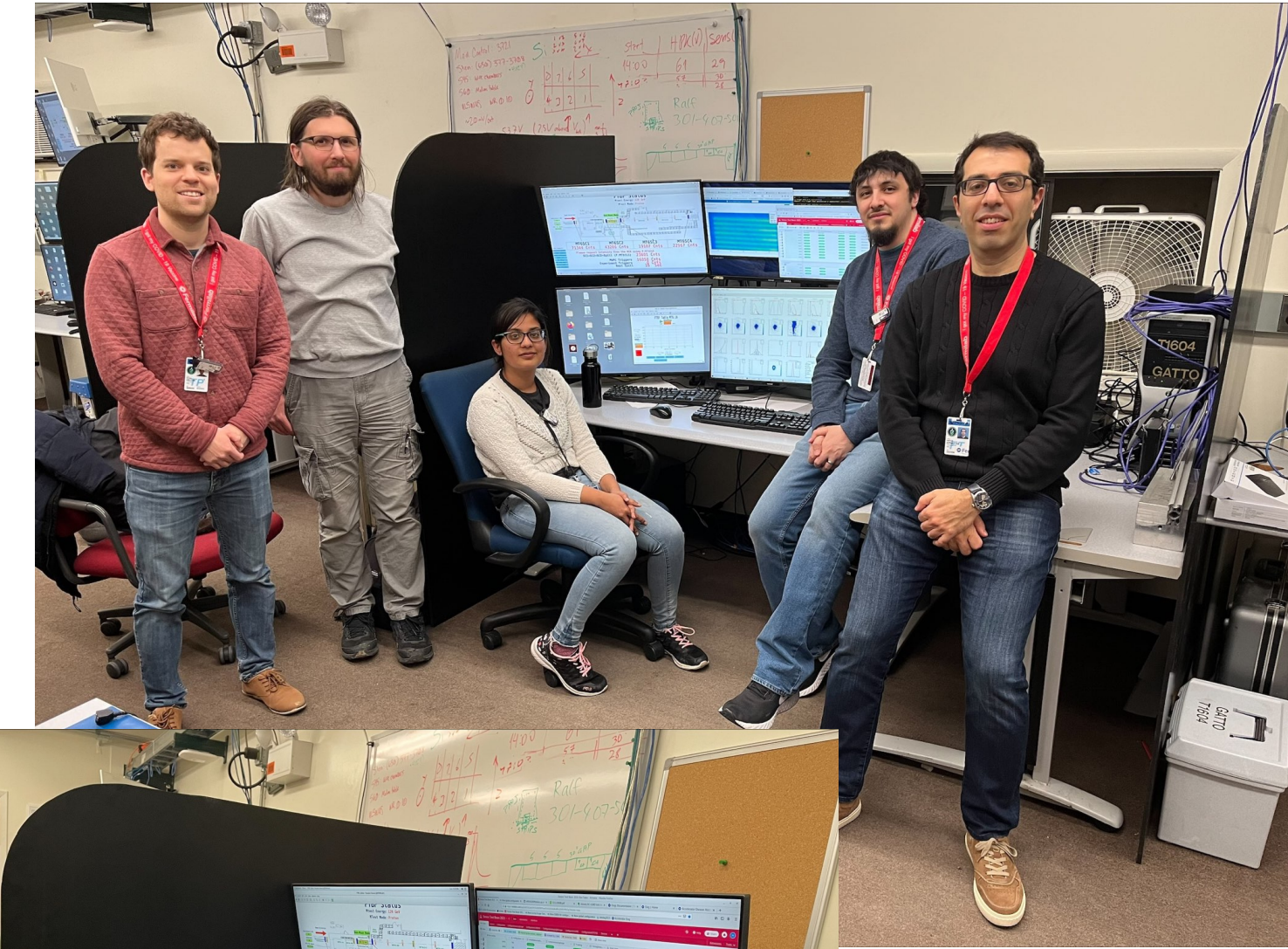
Christopher Madrid

eRD112/LGAD Consortium Meeting

February 22, 2023

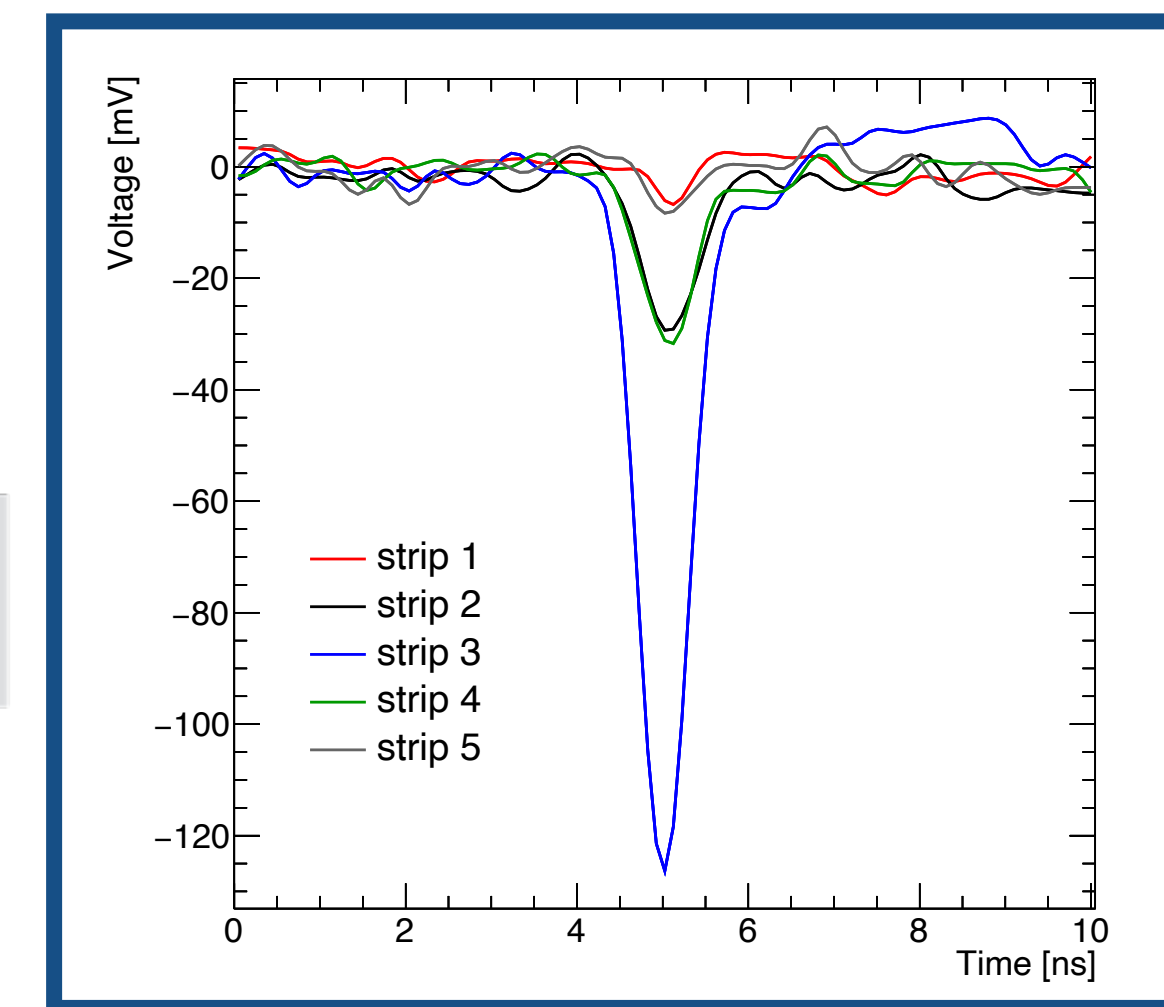
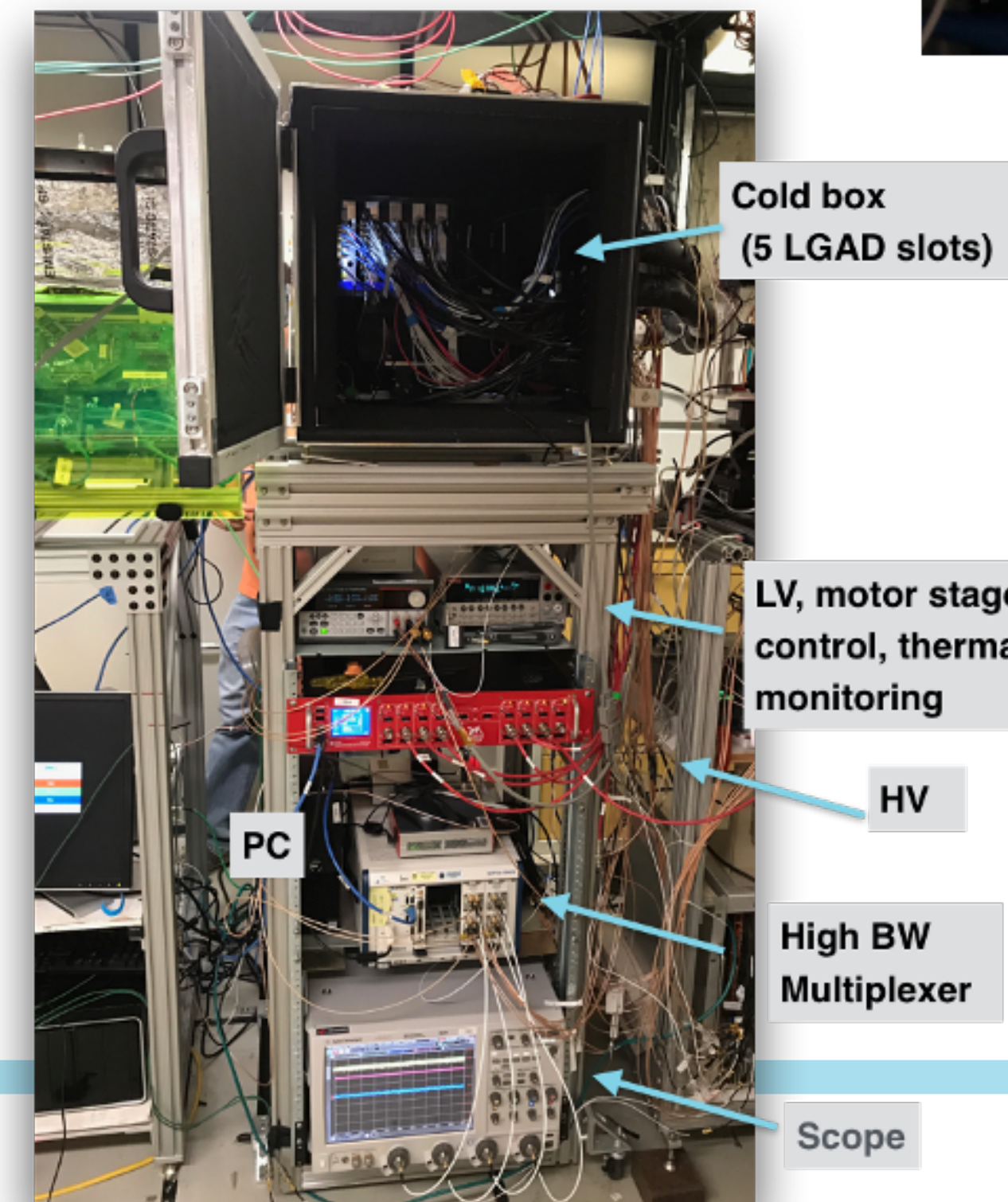
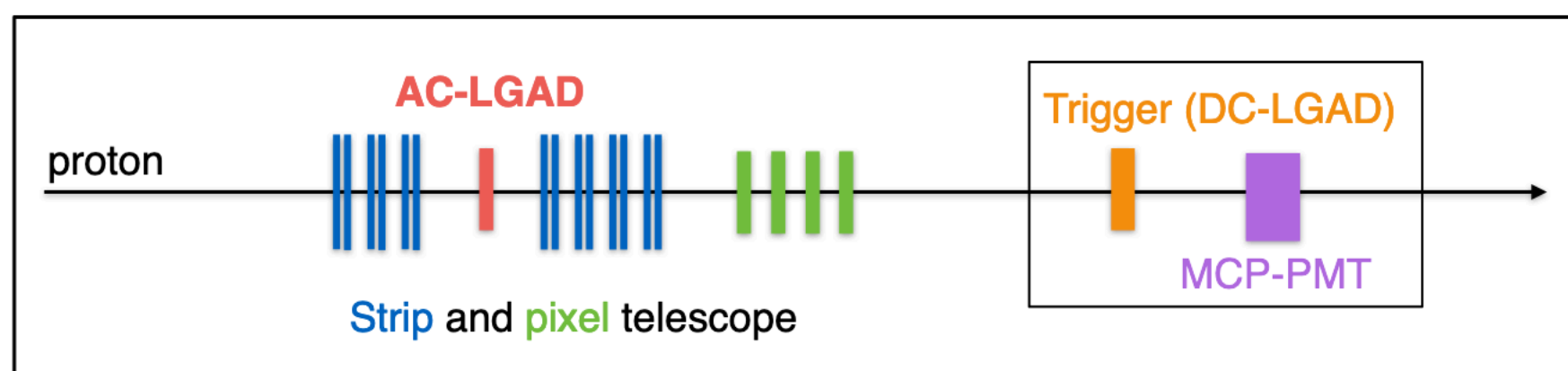
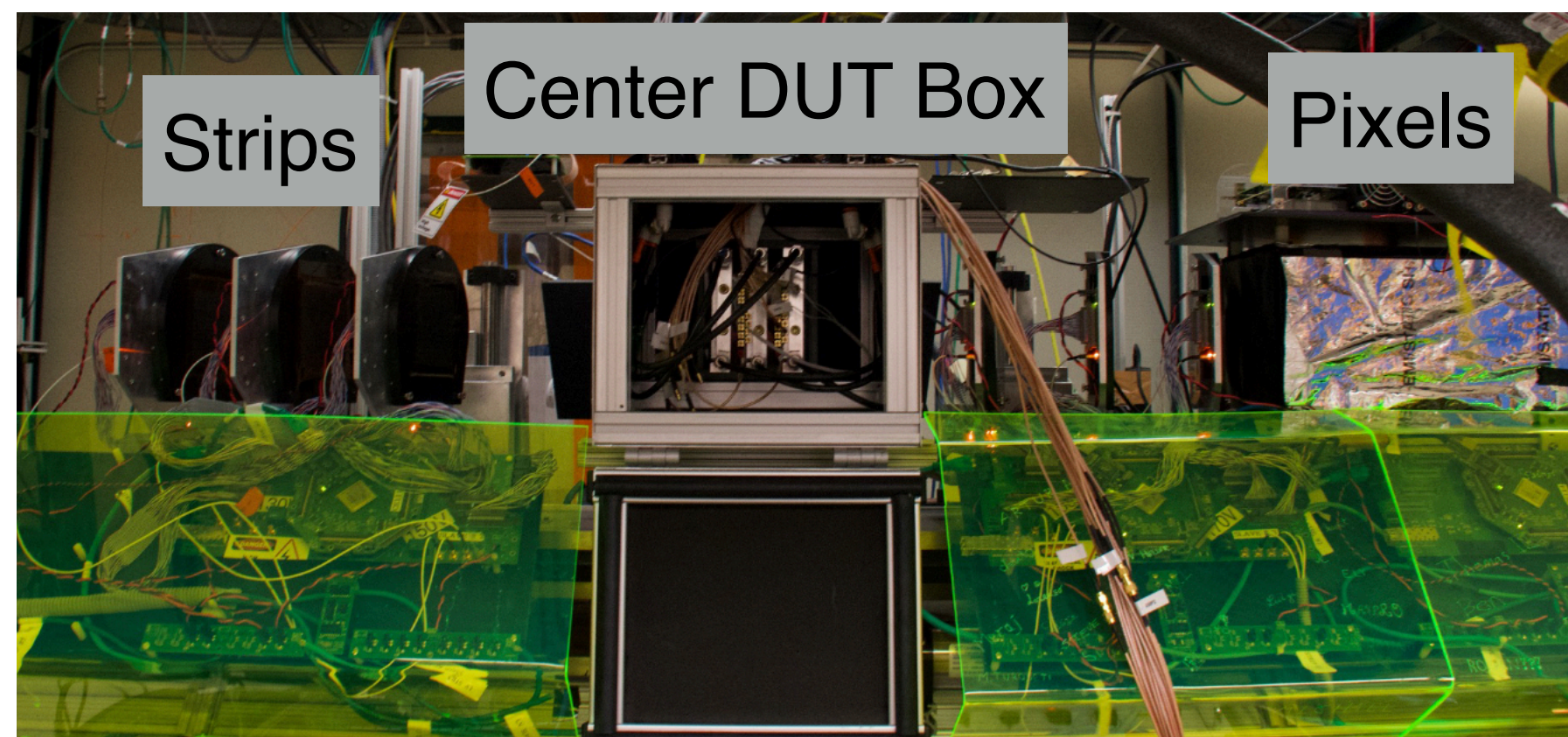
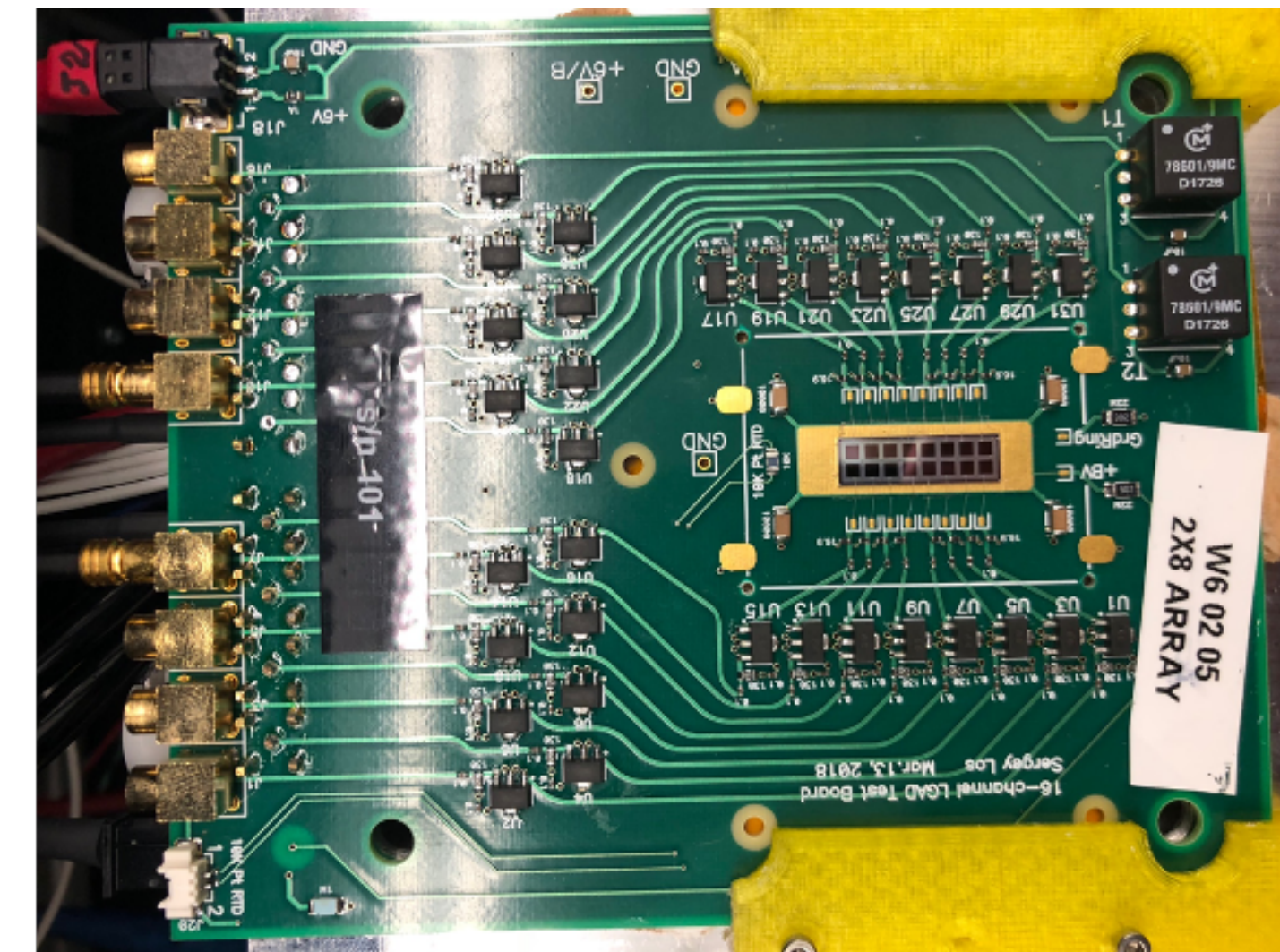
Introduction

- Studying AC-LGAD sensors with 500 μm pitch at the FNAL beam test facility
- Performed a **beam test in March 2022** focusing on first batch of long strip BNL sensors
 - Previous test beam presentation to eRD112 ([link](#))
 - Paper detailing 2022 beam test results ([arxiv.2211.09698](#))
- **Recently concluded another beam test on second batch of long strip BNL sensors and new HPK 500x500 μm^2 pixels**
 - January 4-10th, 2023
- January 2023 beam test measurement goals
 - **Confirm previous performance with uniform gain sensors**
 - **Measure performance with 50 μm width metal electrodes**
 - **Study impact of 50 μm vs. 20 μm active thickness for 1cm length BNL sensors**
 - **Study thickness variation for HPK pixels**

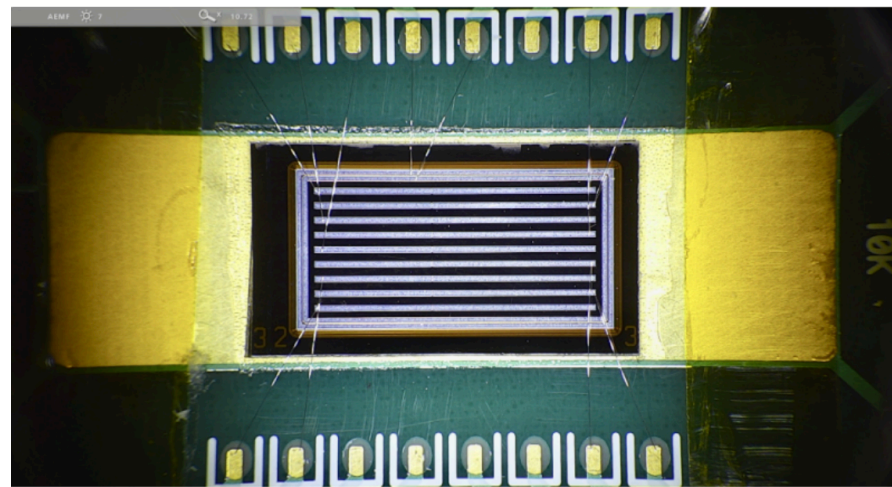


Fermilab 4D-trackers test beam infrastructure

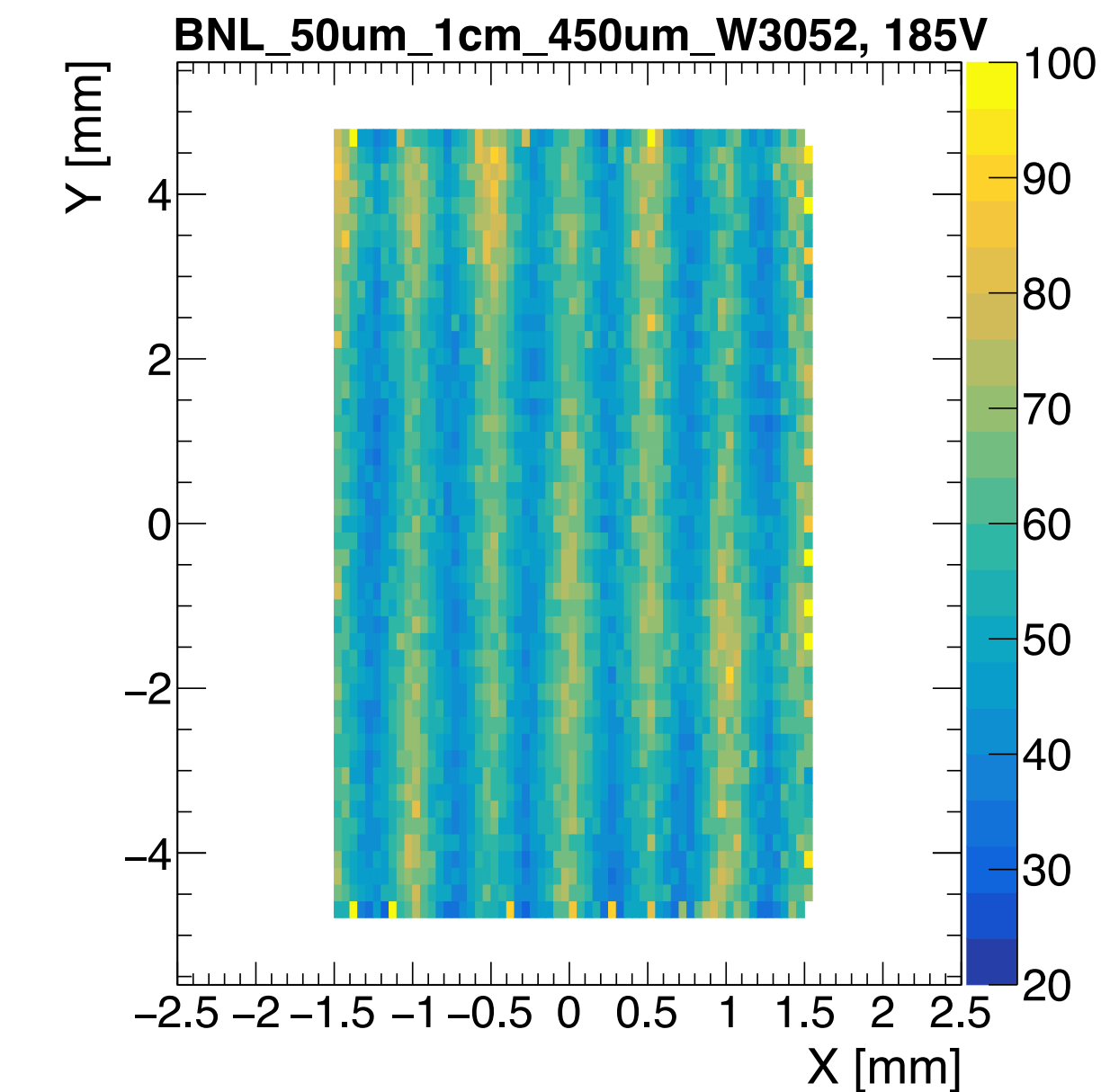
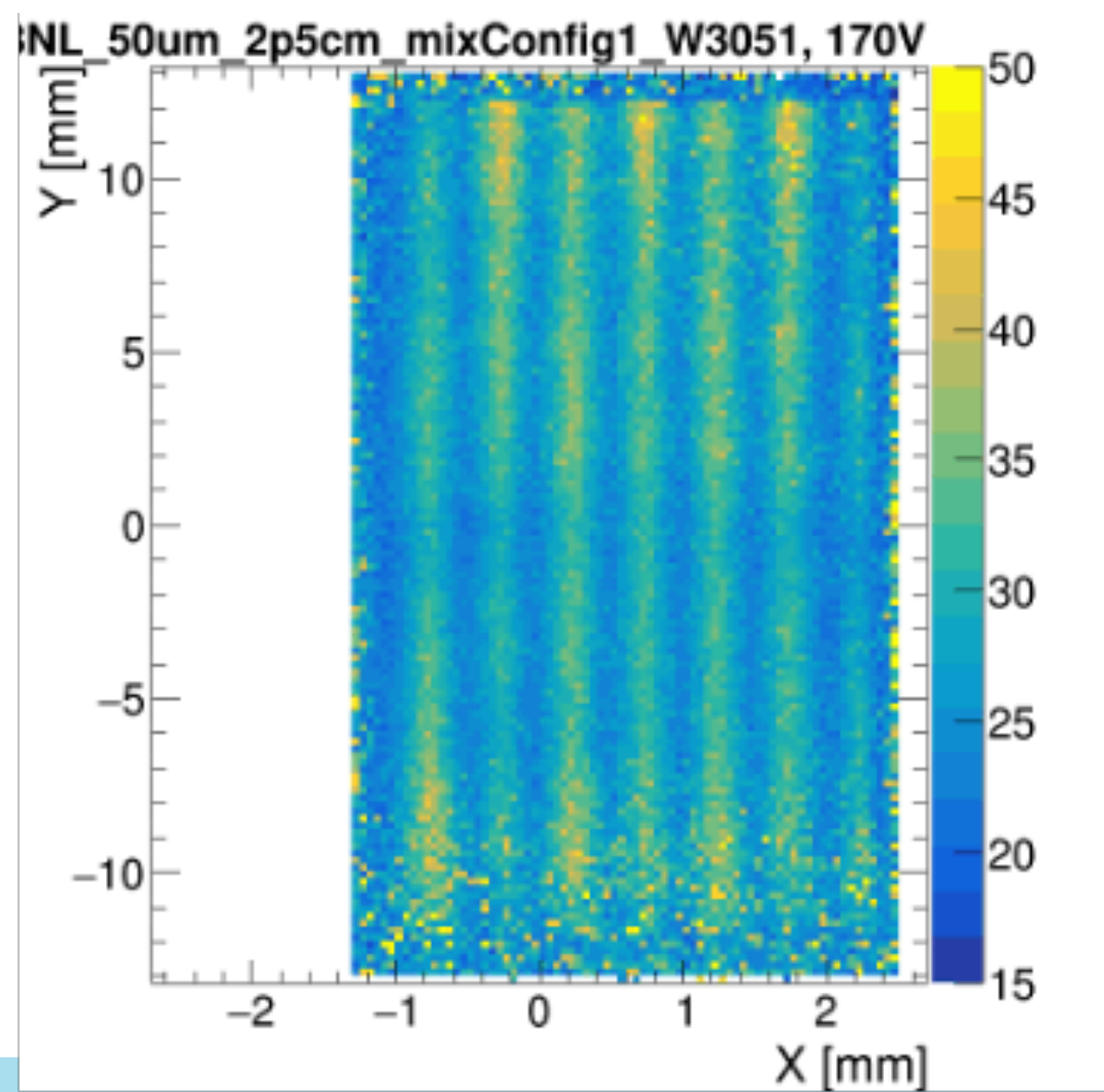
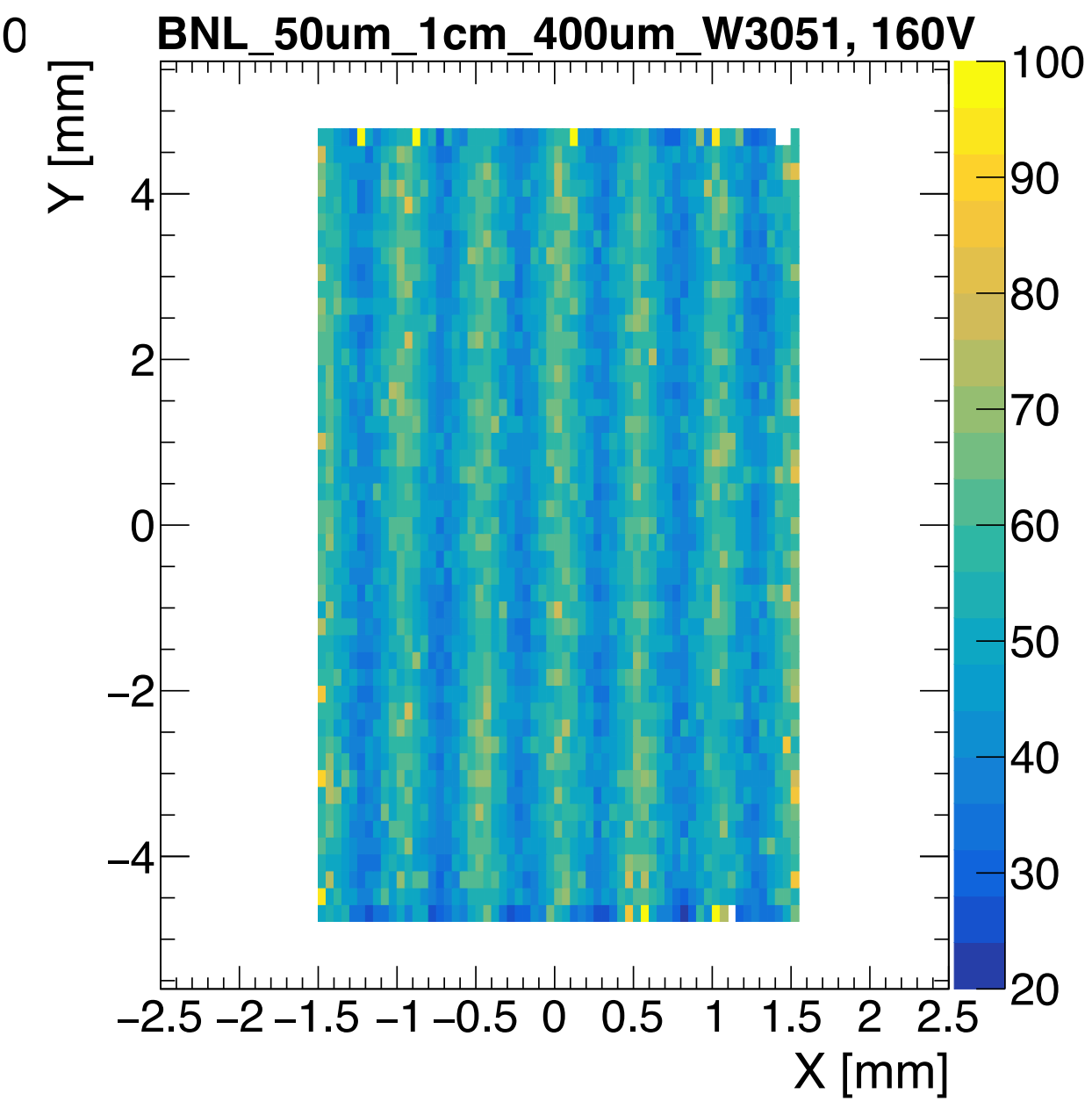
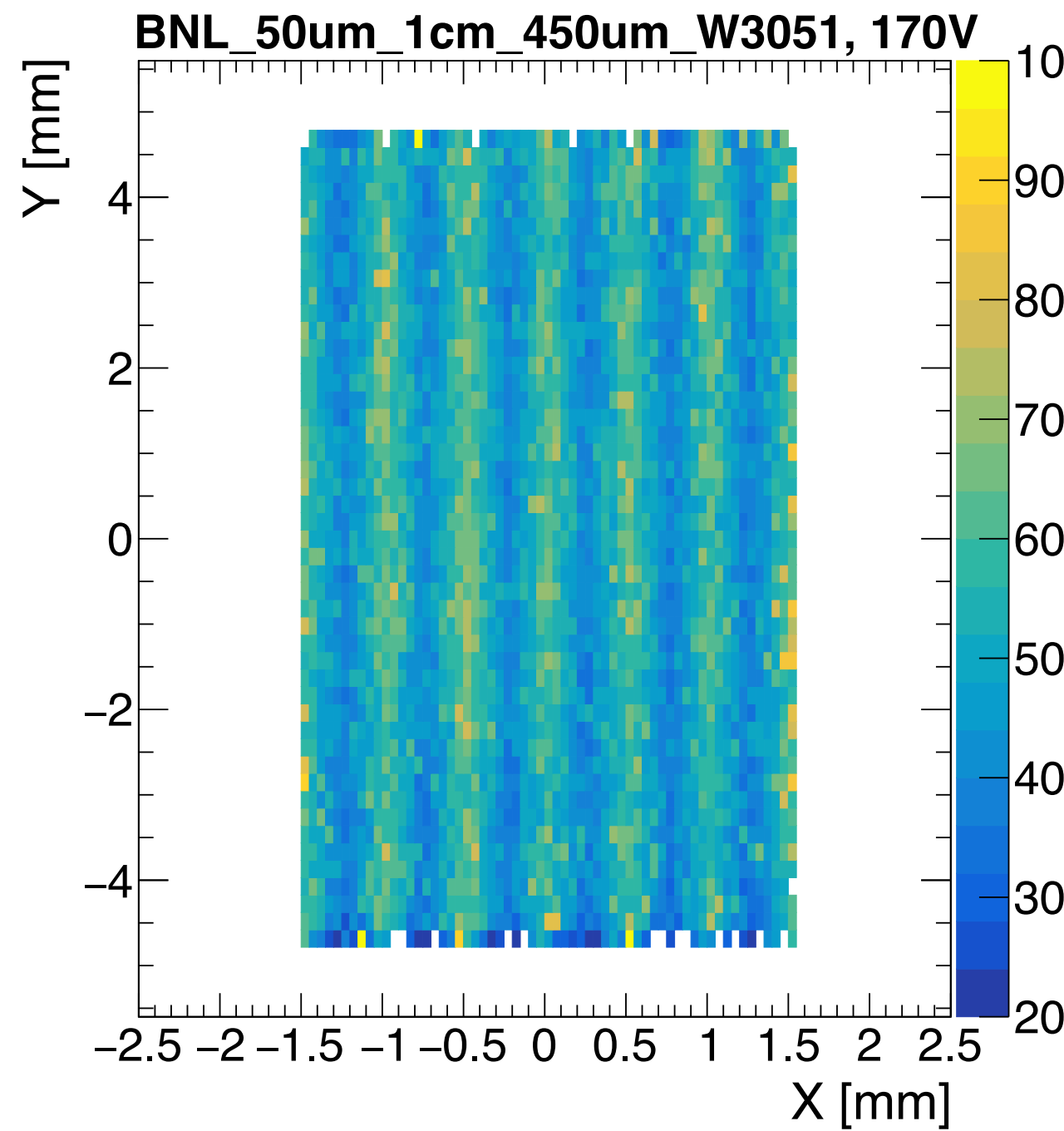
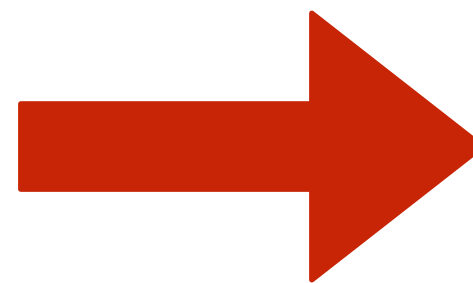
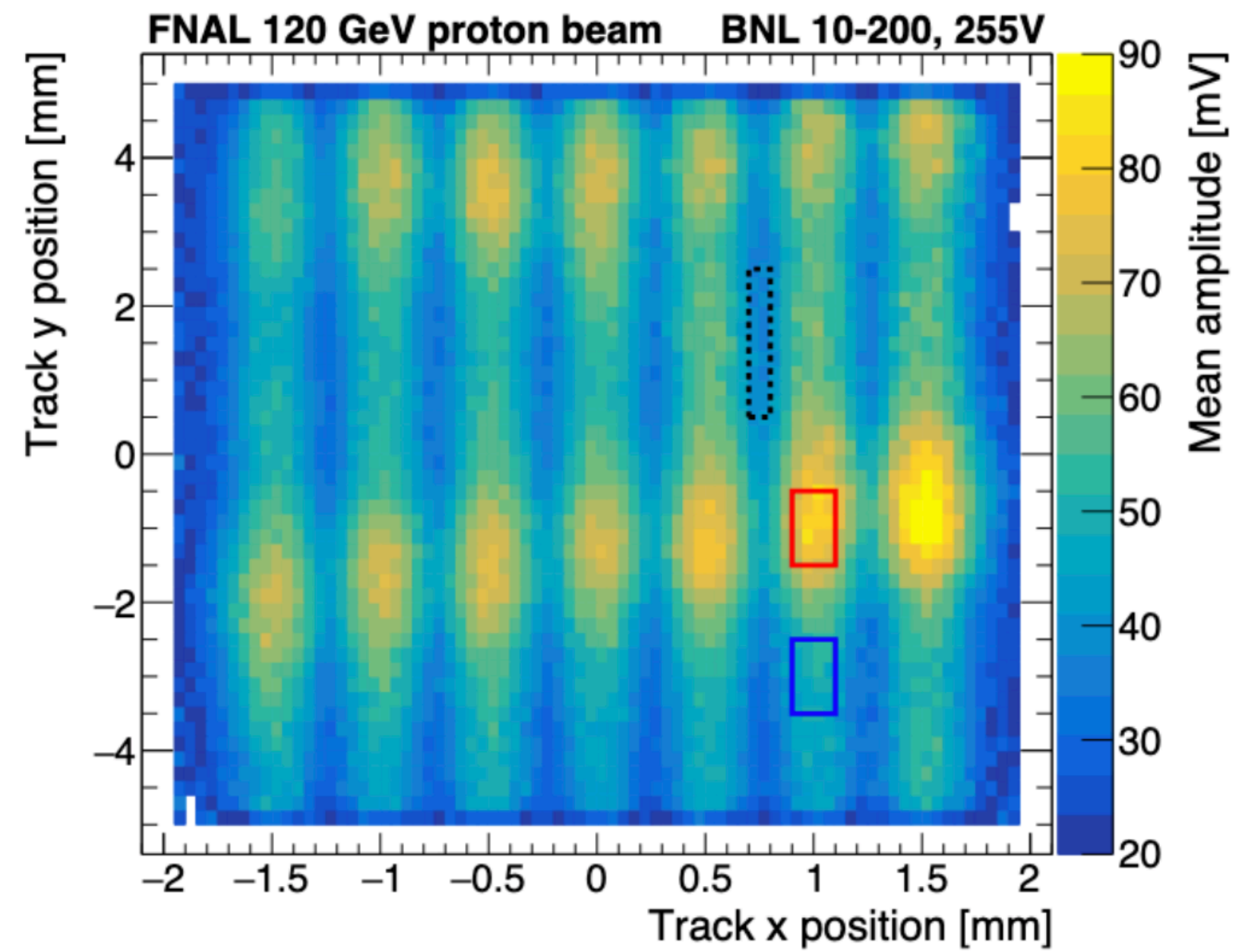
- Permanent setup in FNAL test beam facility (FTBF)
 - Movable: slide in and out of beamline as needed, parasitic use of beam
 - Environmental controls: sensor temperature (-25 C to 20 C), and humidity, monitoring
 - Remote control (stages, HV, LV), logging & reconstruction; $\sigma T \sim 10$ ps time reference (MCP)
 - Cold operation of up to 10 prototypes at the same time
 - DAQ: high bandwidth, high ADC resolution scope 8-channel scope
 - Record 100k events per minute, tracker with ~ 5 μm resolution
- Developed readout boards for the characterization of LGADs
 - Without complicated ASIC and DAQ



Check gain uniformity

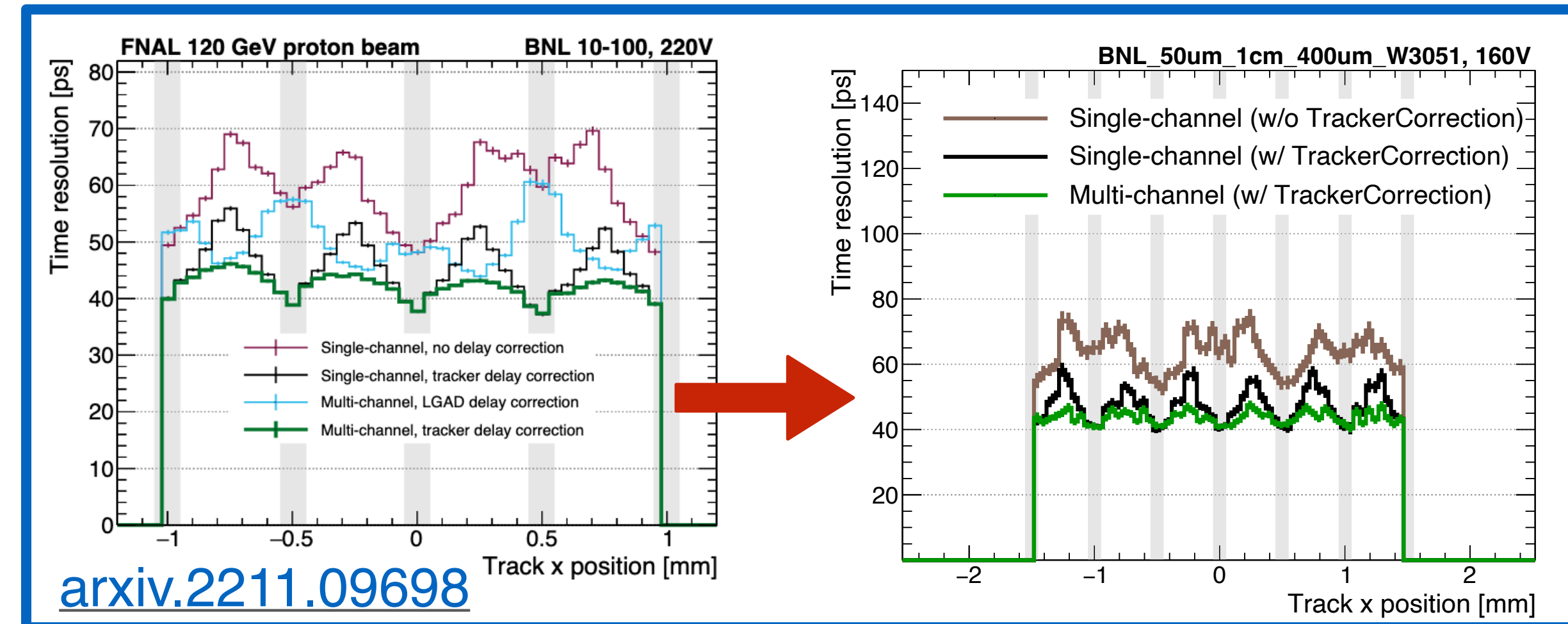
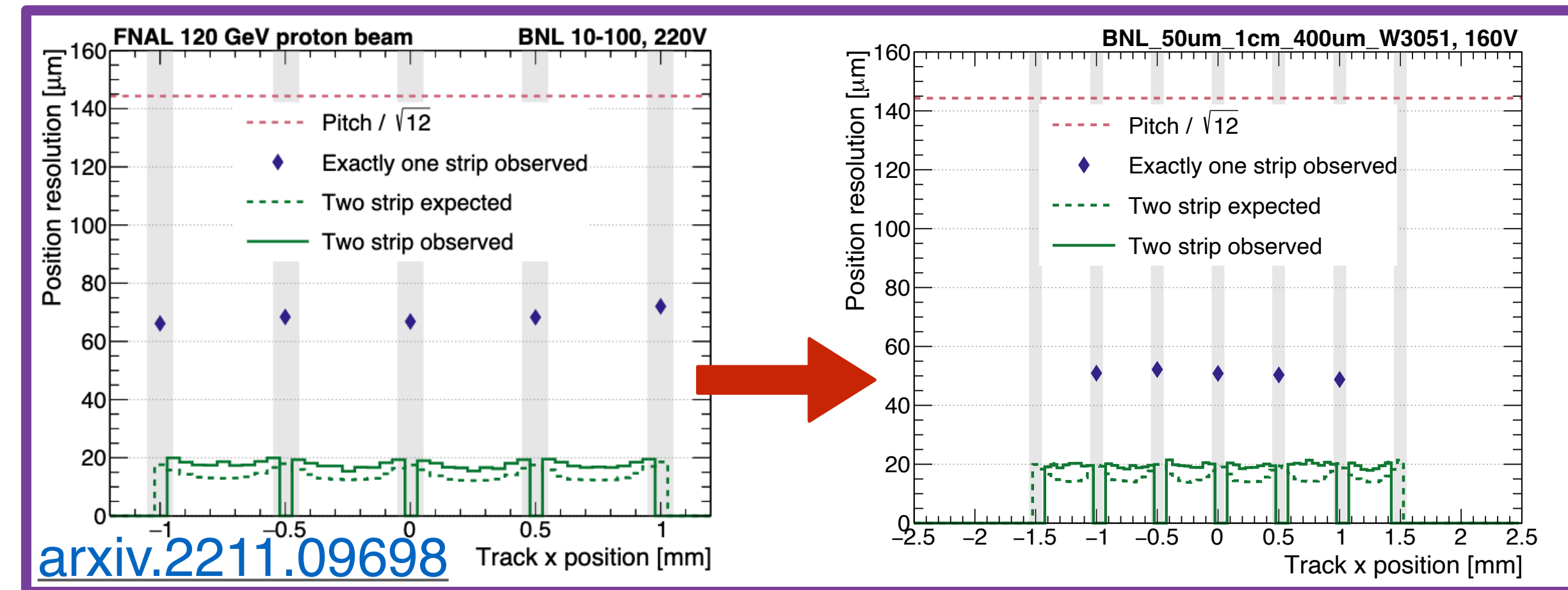
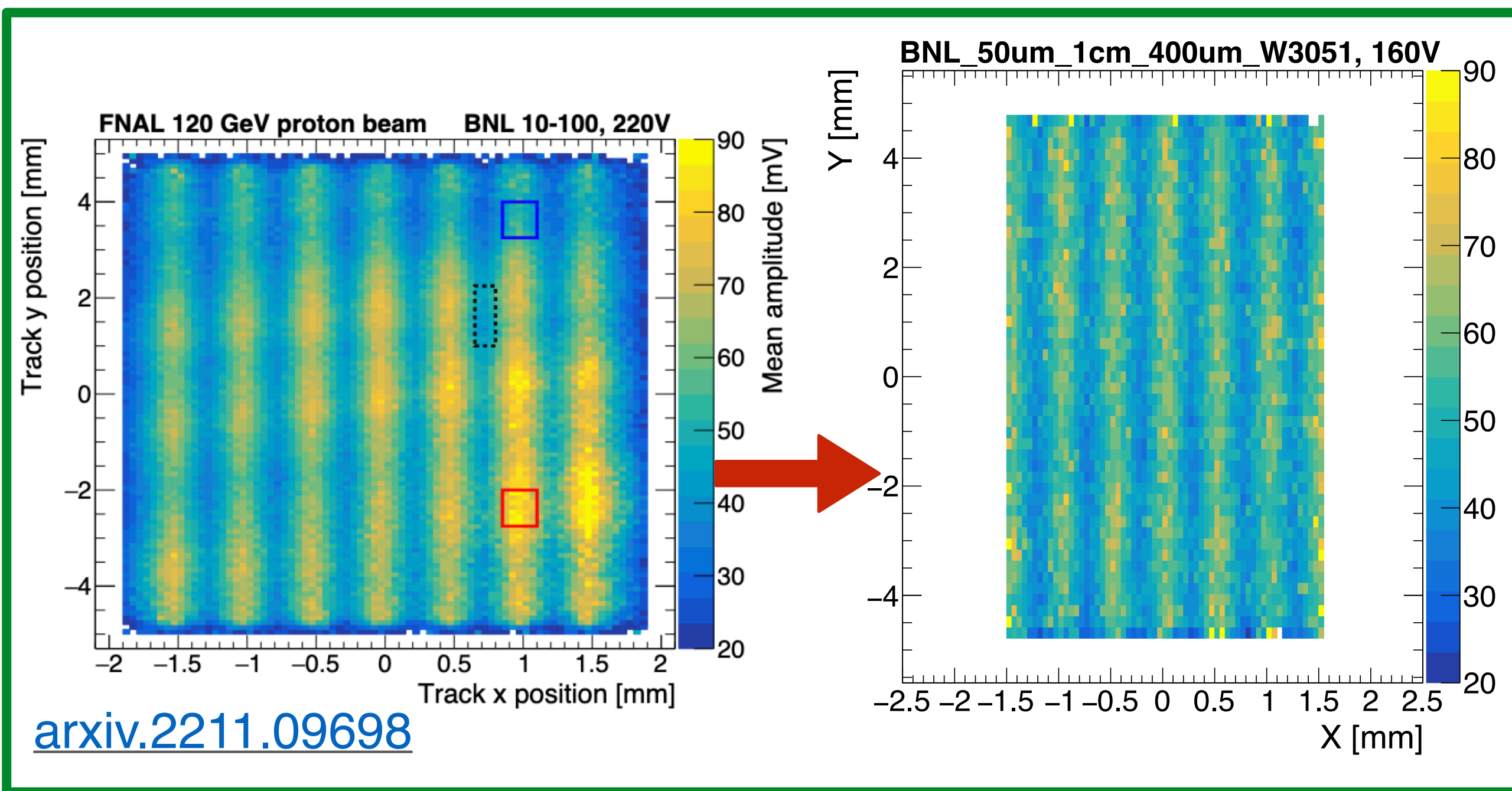


[arxiv.2211.09698](https://arxiv.org/abs/2211.09698)



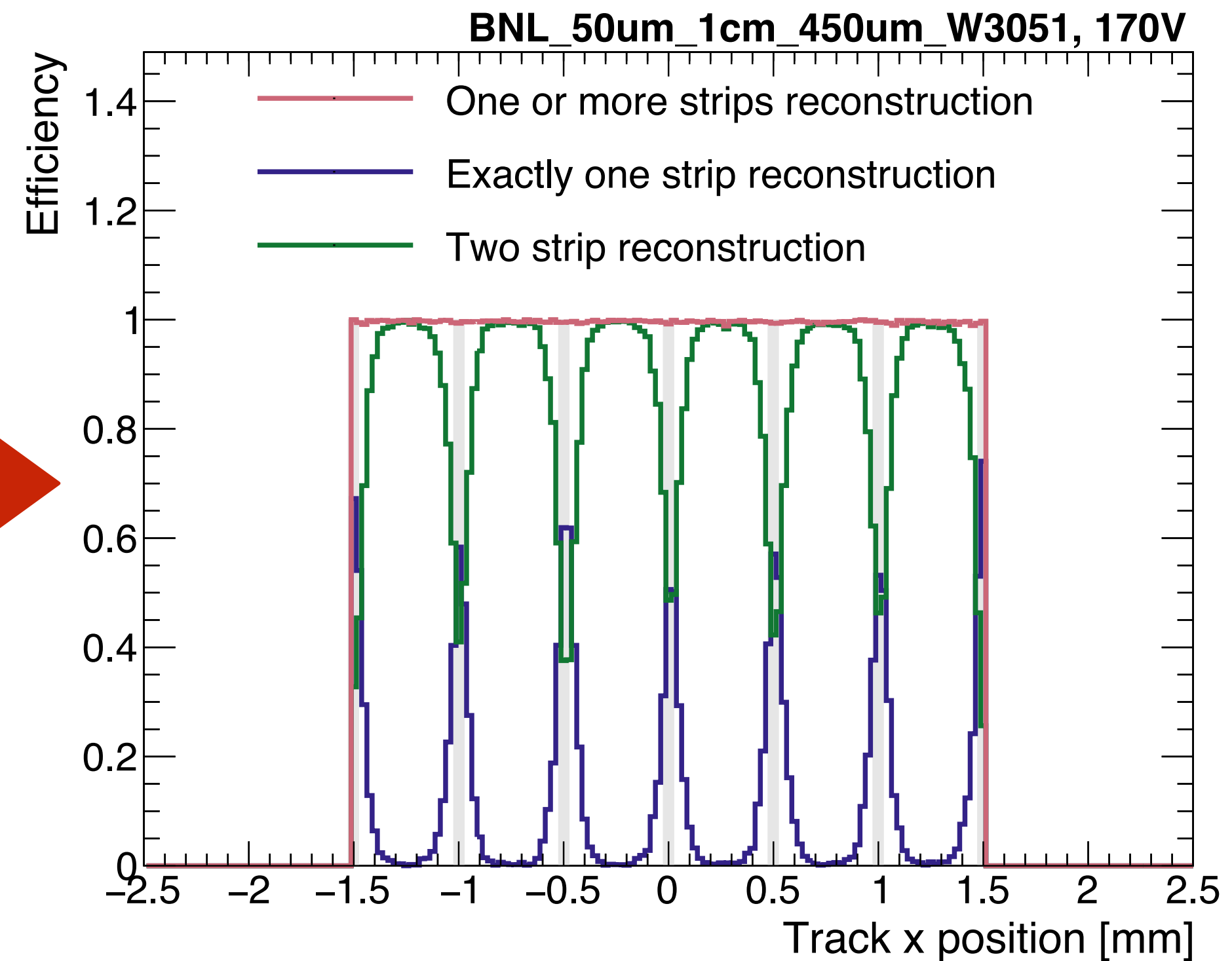
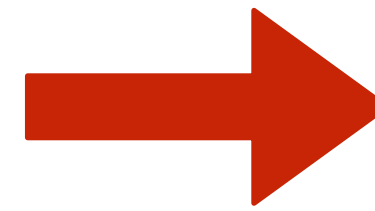
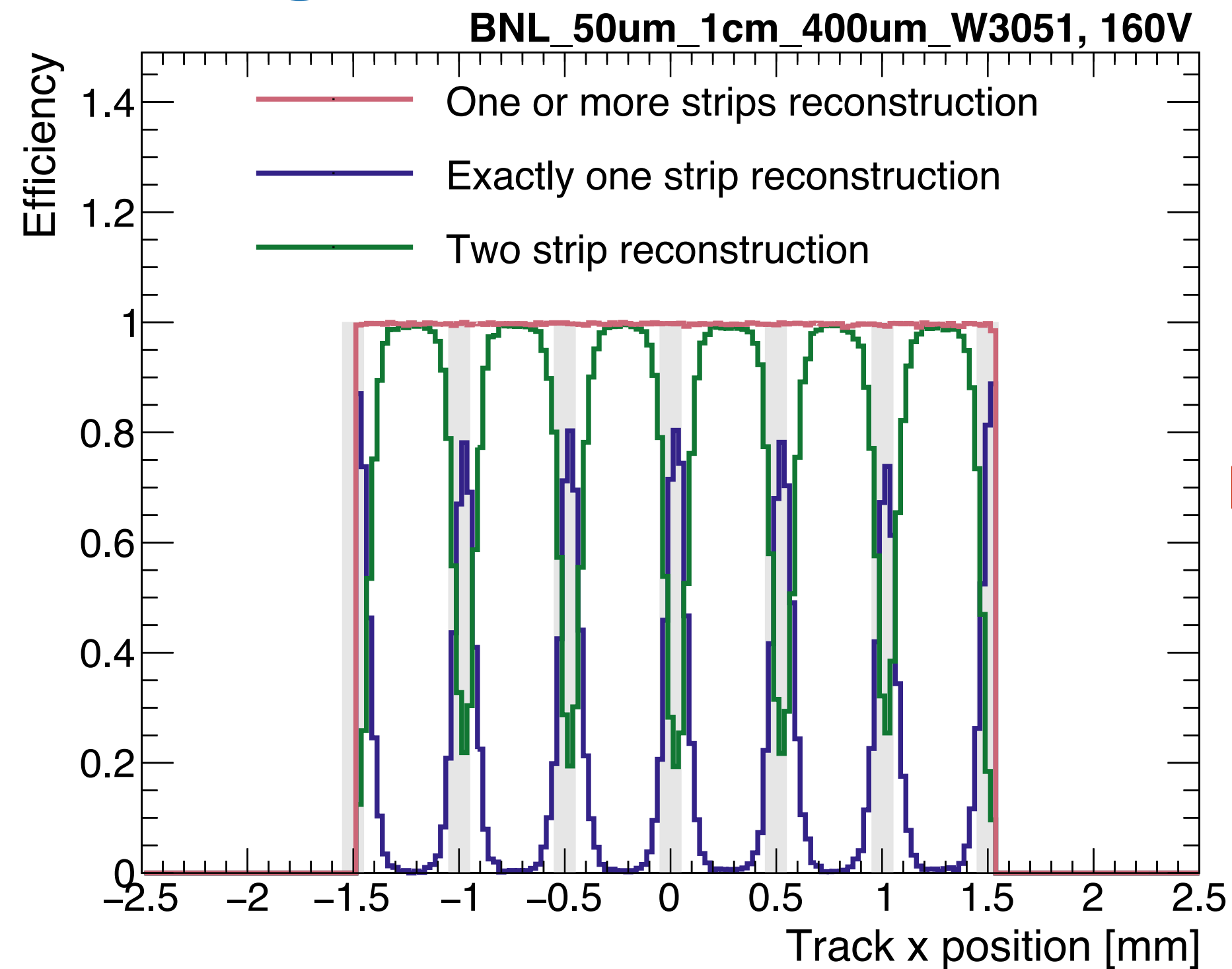
- Greatly improved gain uniformity from **first** BNL large sensor batch compared to **second**
- Operating voltage lower for new batch of sensors

Reproduce previous results



- Signal **amplitude** has decreased for new production
- Similar, **time** and **position** resolutions
- Should be able to build on previous measurements to understand new sensor thickness

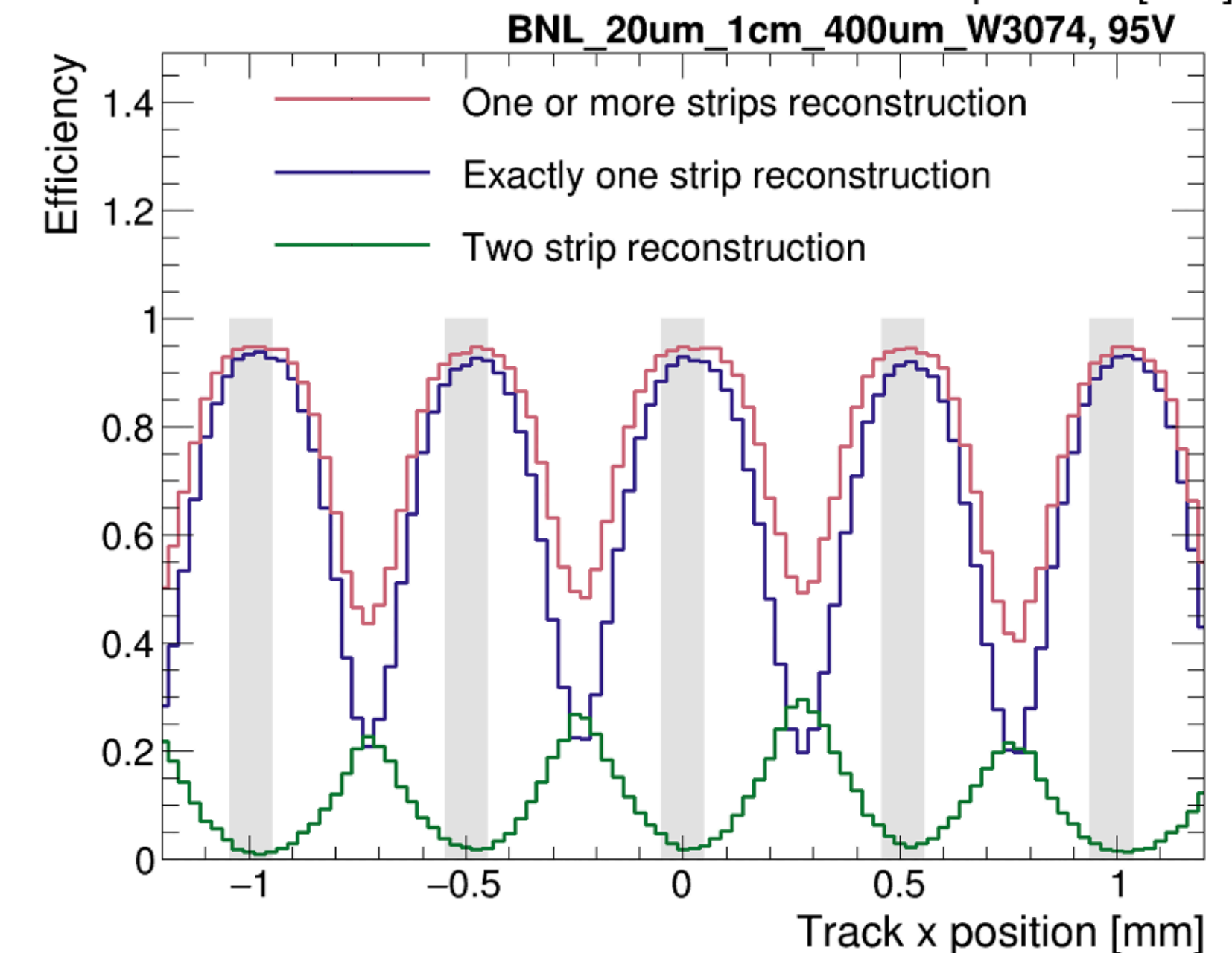
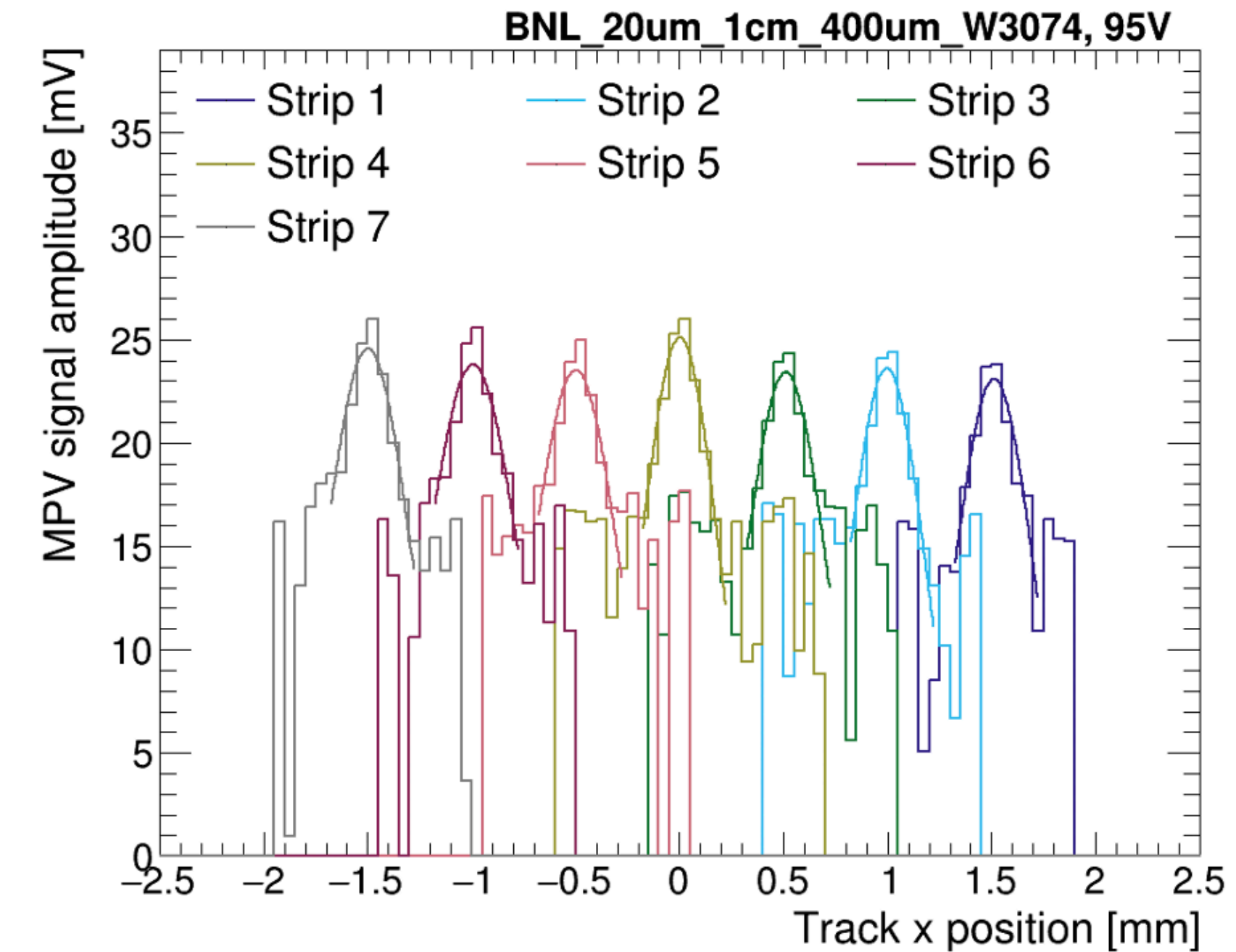
Comparing 400 vs. 450 μm metal electrode size



- For 1 cm length sensors conjectured that smaller metal would improve 2 strip efficiency and smooth overall position resolution
- Observe similar signal amplitude, time and position resolution
 - However, did not reach same operating voltage
- **Small improvement to 2 strip efficiency 81% vs. 87%**
- Still studying differences but overall very similar

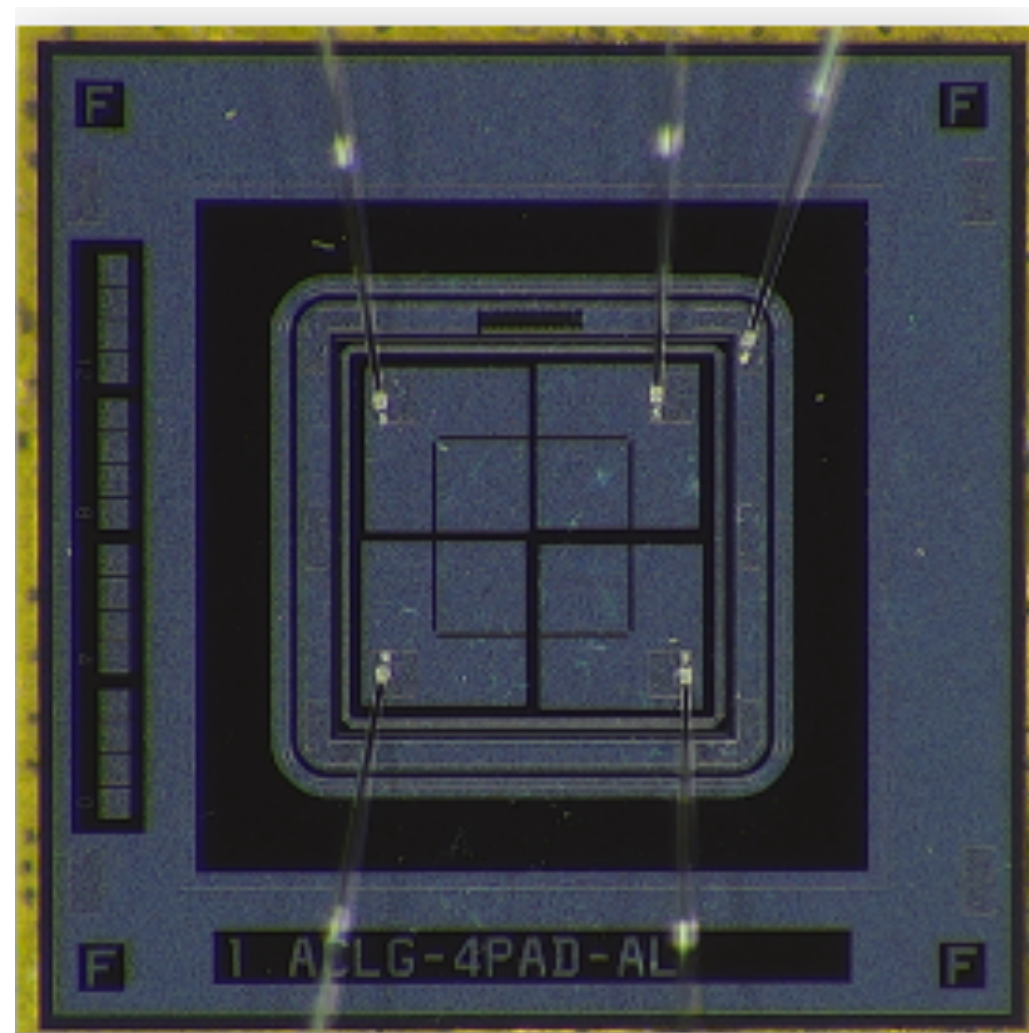
Studying 20 μm thick sensors

- At what point are you signal to noise limited vs. Landau limited for the time resolution when varying sensor thickness?
 - If Landau limited on time resolution can try thinner sensors
 - Expect $\sim 2/5$ smaller signals for 20 μm compared to 50 μm sensors (60 mV \rightarrow 24 mV)
- **Results for best performing BNL 1cm length 20 μm**
 - Observe ~ 25 mV signals for direct metal hits
 - ~ 65 mV signals for 50 μm version
 - Do not see usable signals in the gaps
 - **Sensor is not fully efficient at 15 mV threshold**
- Worth studying 30-40 μm thick BNL sensors in the future?

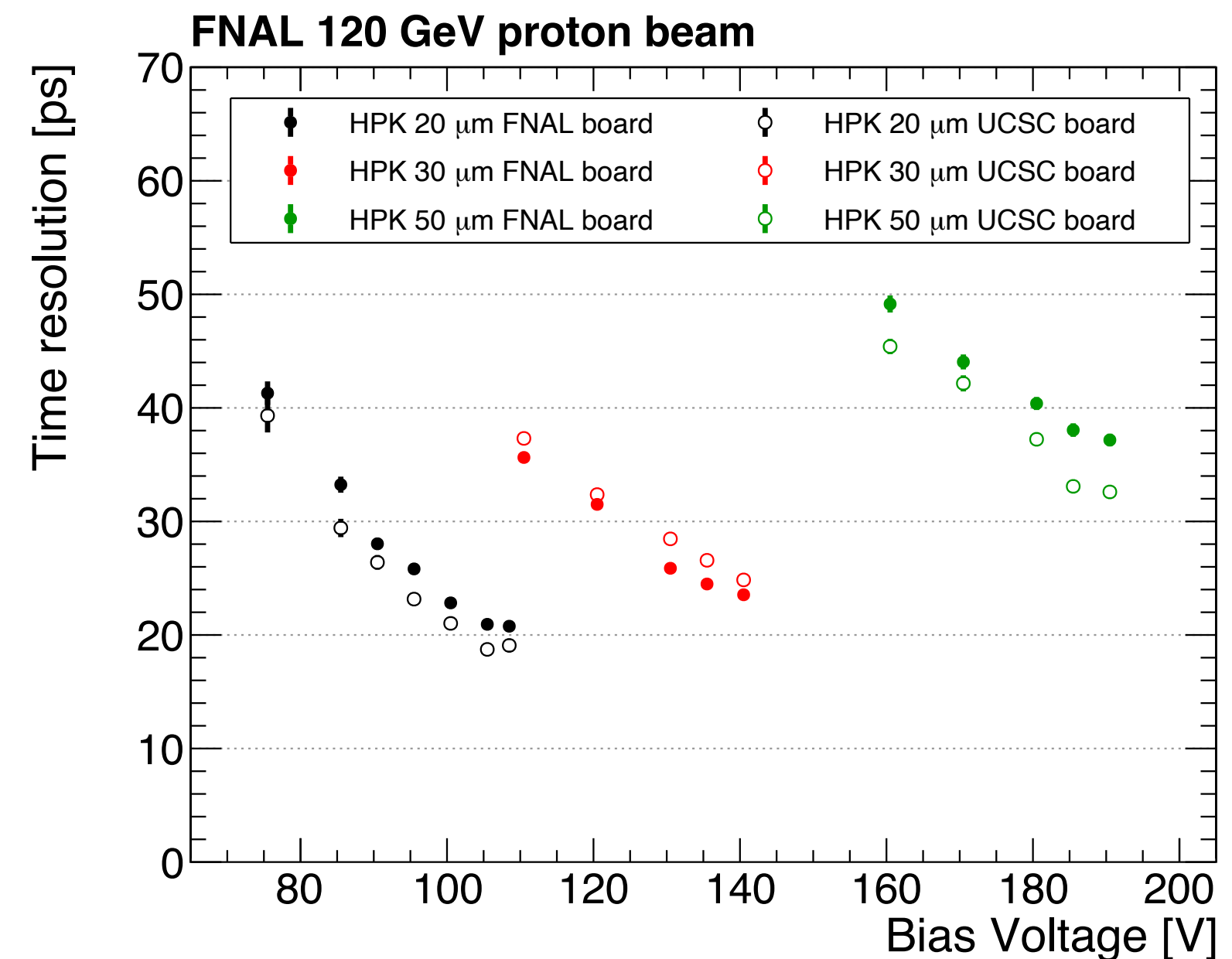
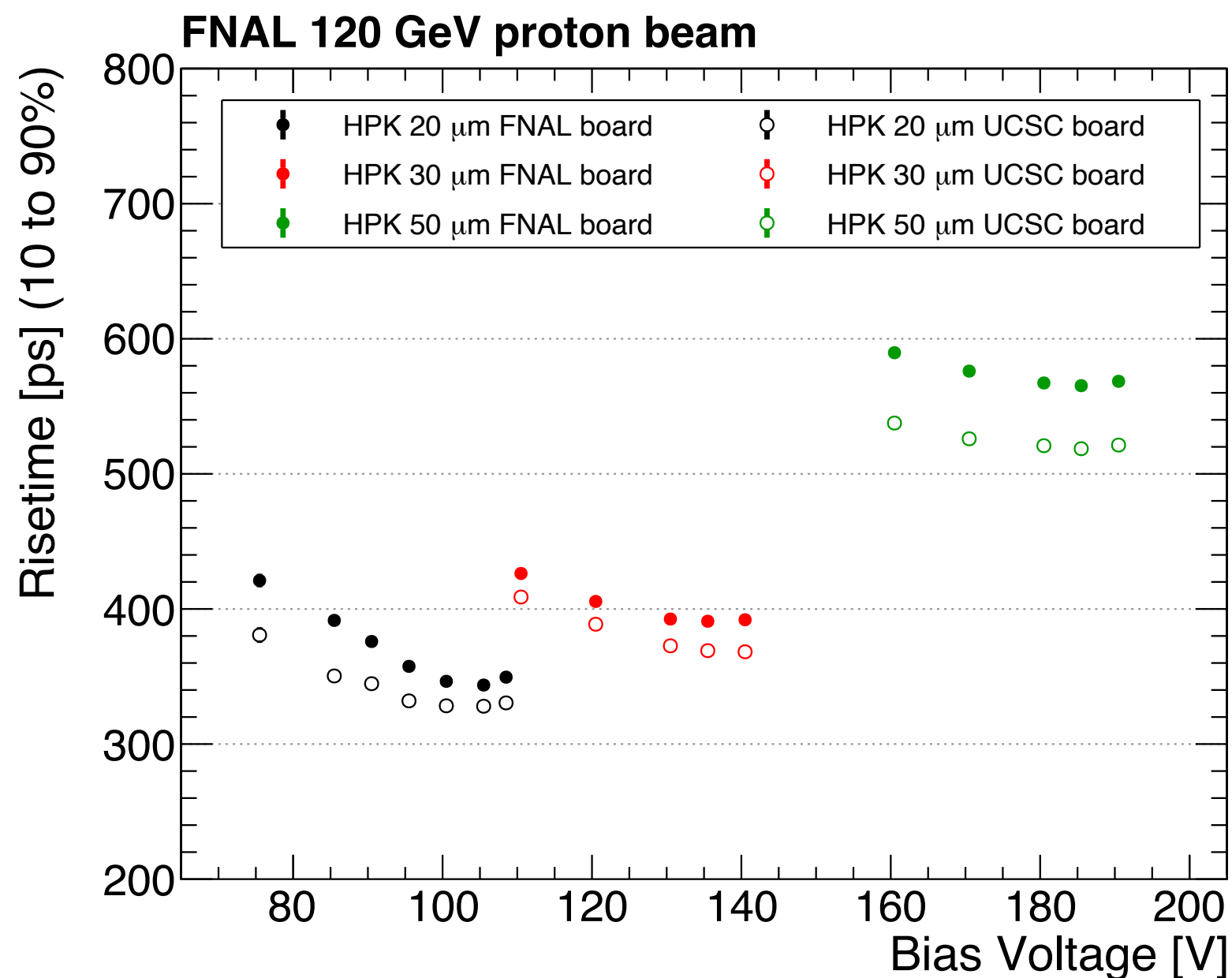
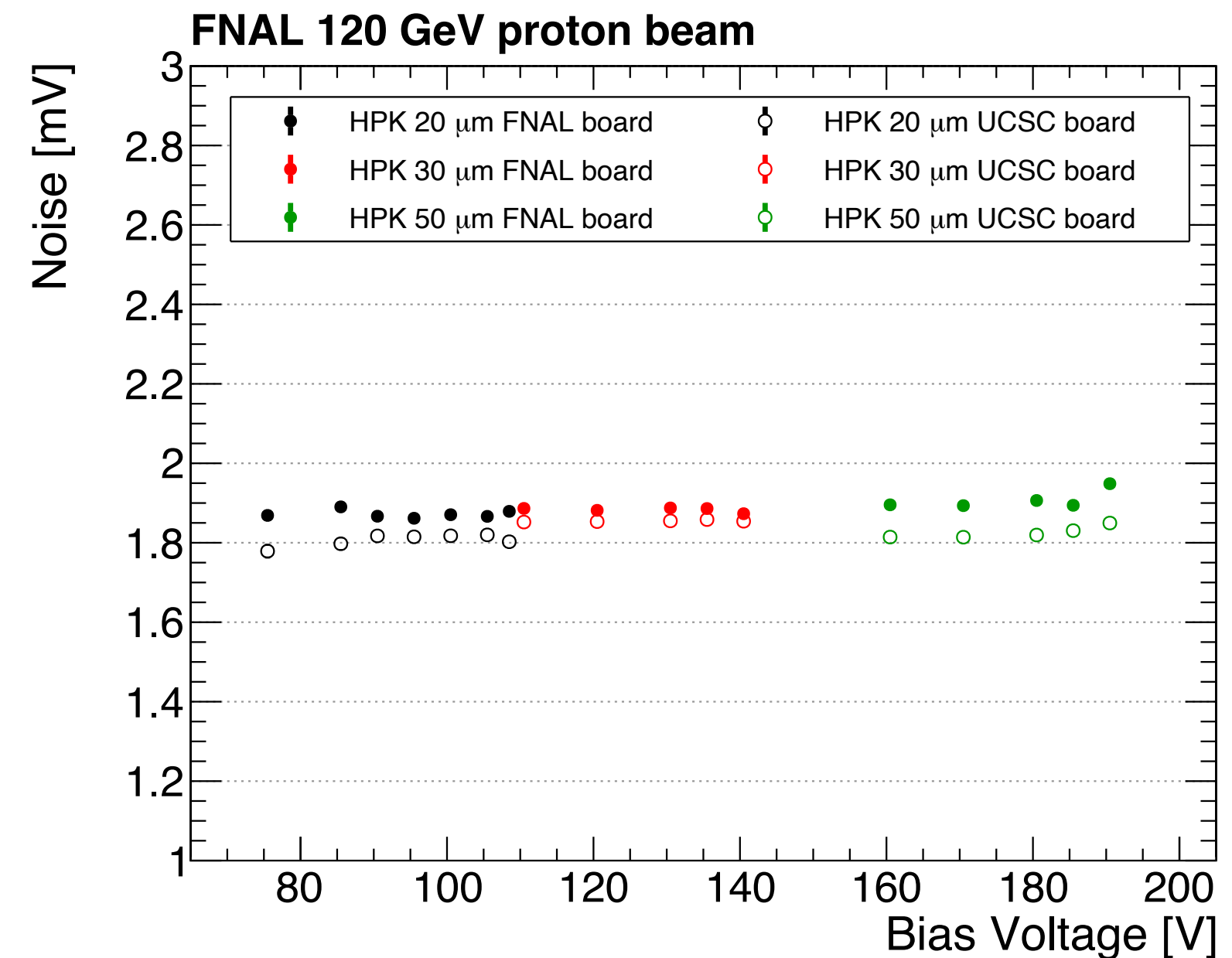
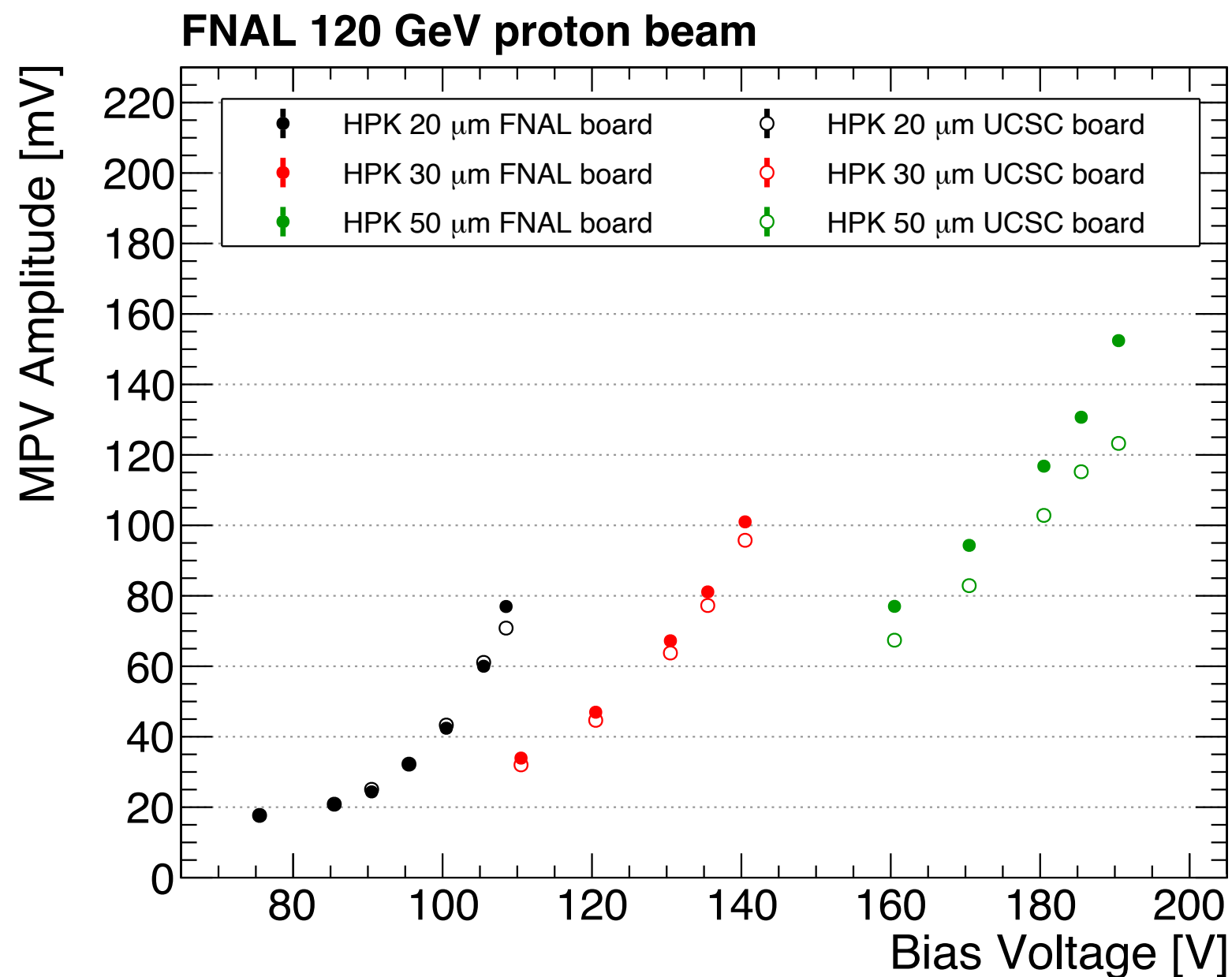


HPK sensor thickness variations

- **Results for HPK sensors that are 20, 30, and 50 μm thick**
- 500x500 μm^2 channel size
- Observe great timing performance
 - ~ 20 ps for 20 μm thick sensor
 - ~ 25 ps for 30 μm thick sensor

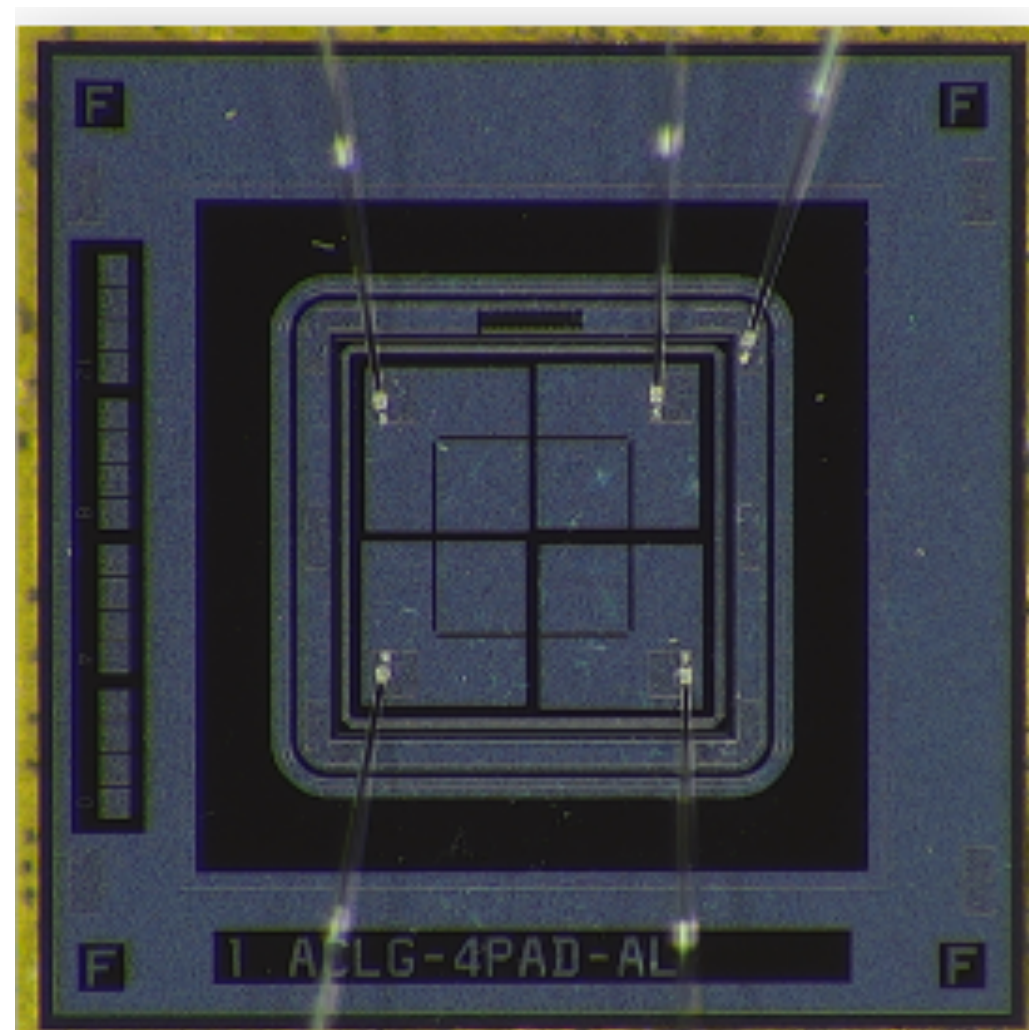
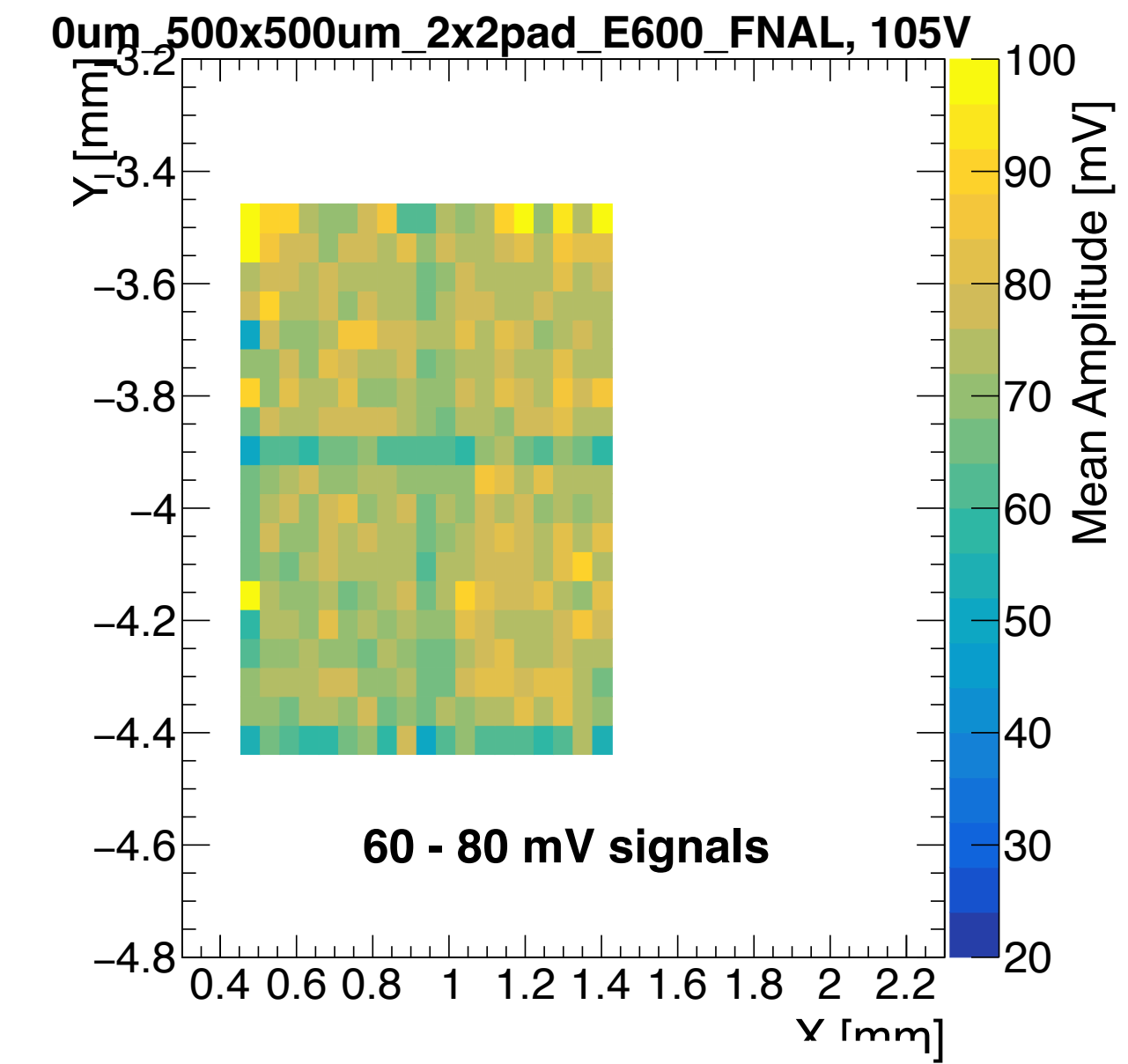
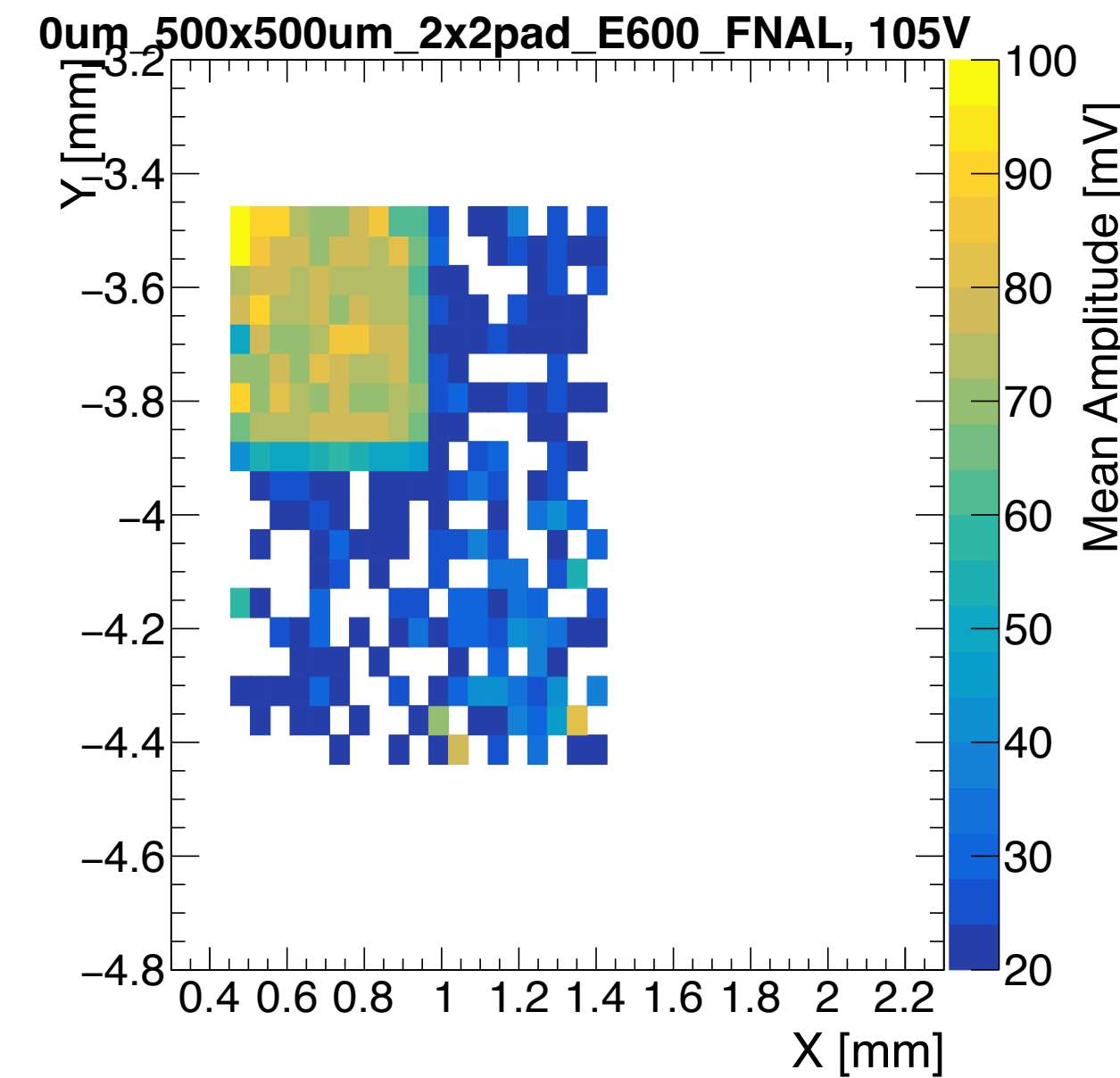


HPK 2x2, 500 μm pad size

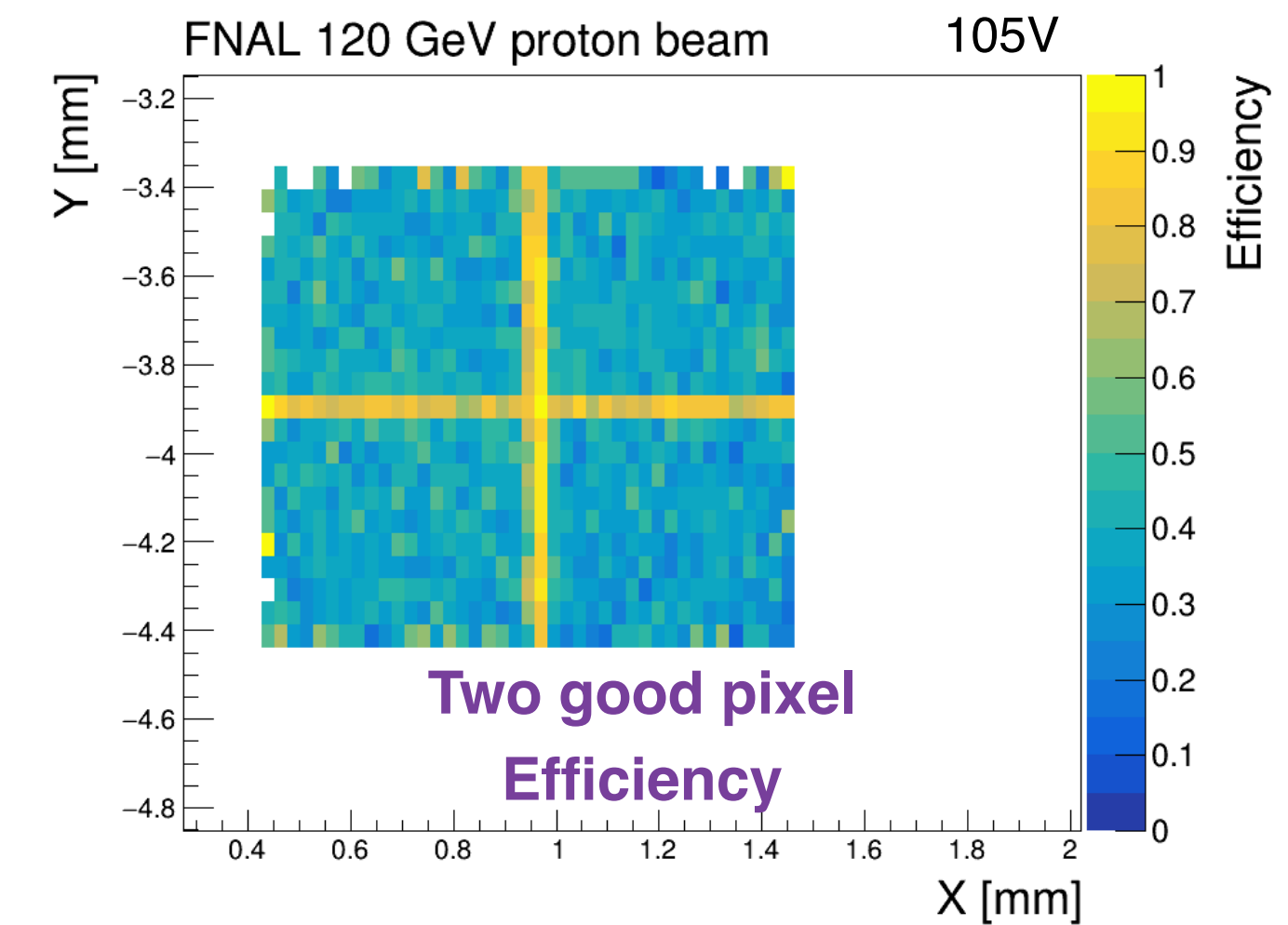
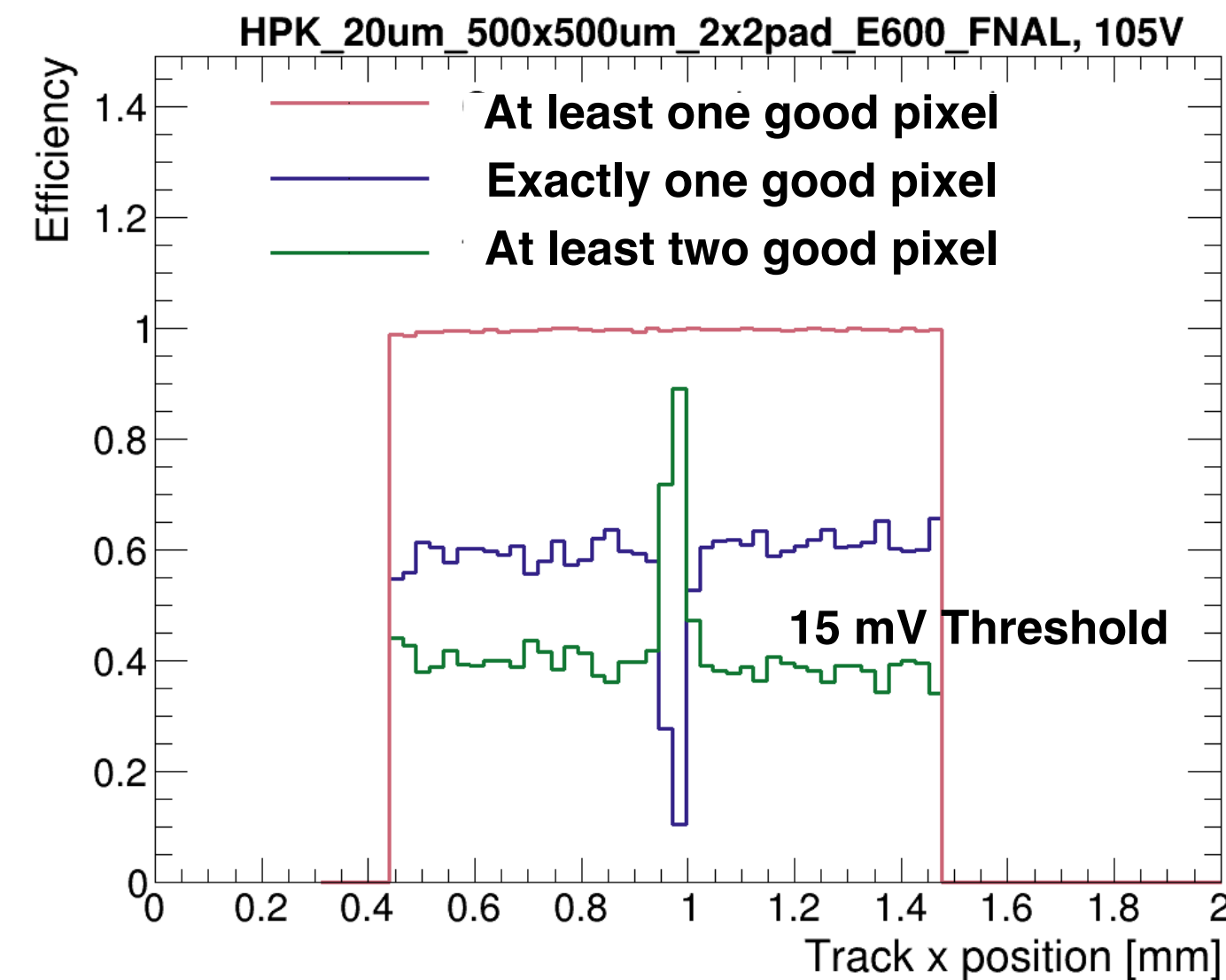


HPK 20 micron results

- **Can not use signal sharing for position reconstruction**
- Do not have 2 pixel efficiency outside of the small non-metallized gaps
- Almost fully metallized
- Optimized for timing performance
 - Higher resistivity

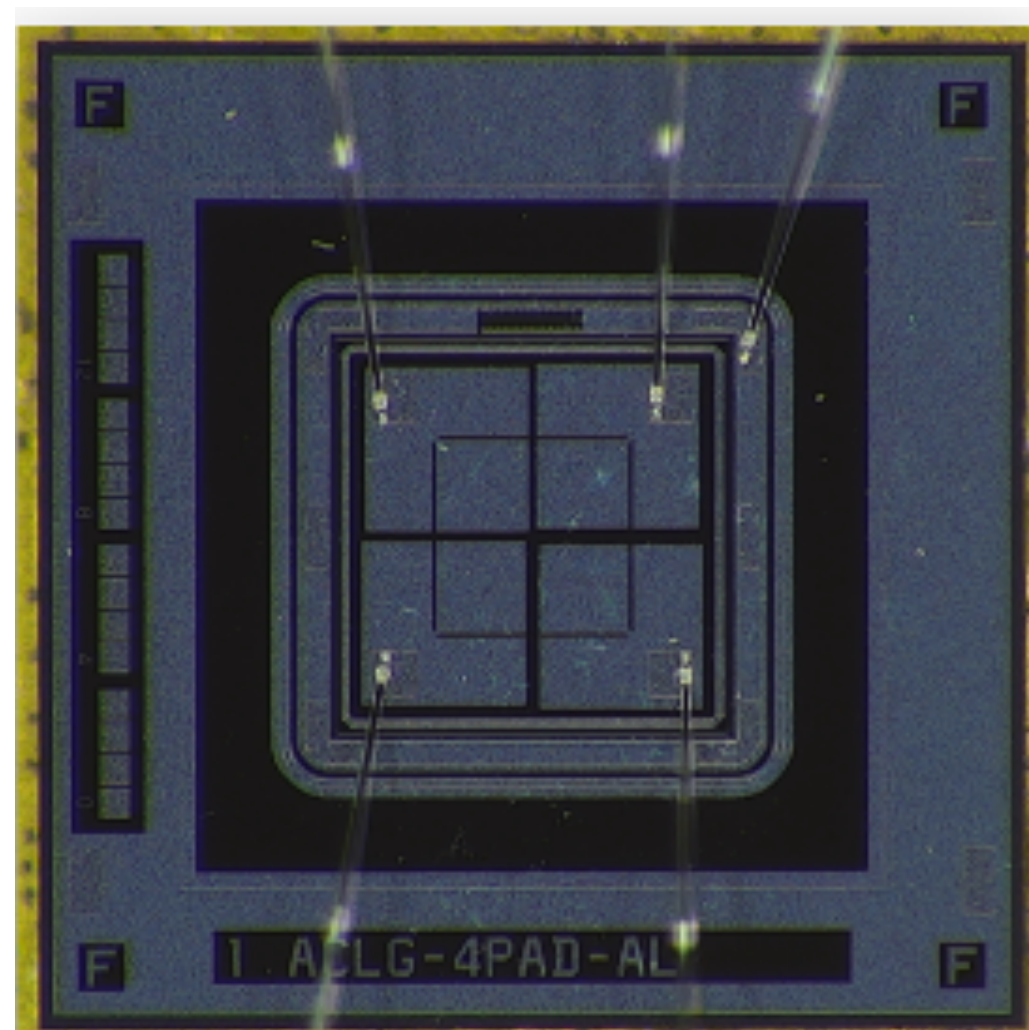


HPK 2x2, 500 μm pad size

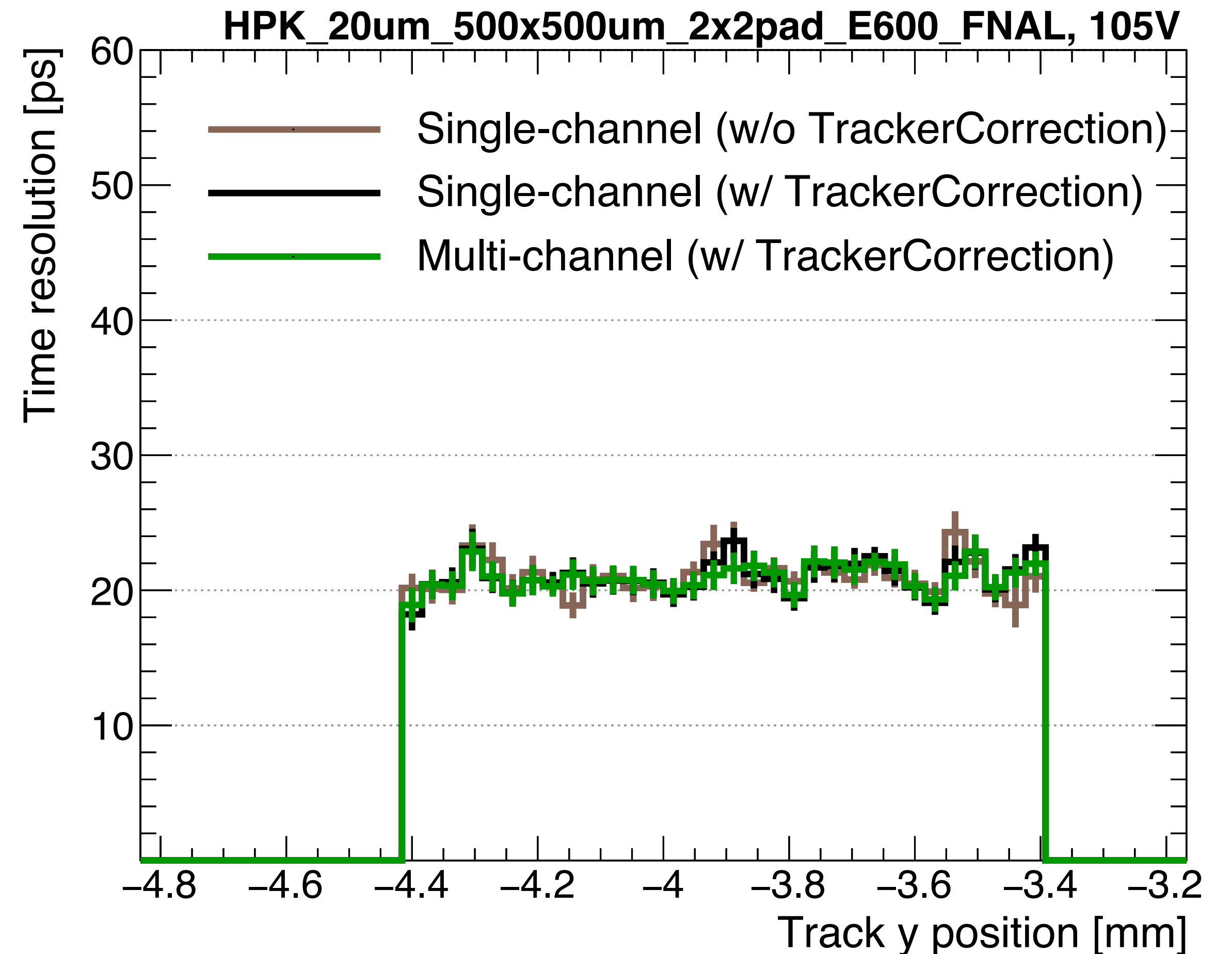


HPK 20 micron results

- Enough signal sharing to cover gap fully
 - Not enough for position reconstruction
- **Observe uniform time resolution across full sensor area**



HPK 2x2, 500 μm pad size



Preliminary Conclusion

- **New batch of BNL sensors have greatly improved gain uniformity**
- Observe similar performance to previous batch for the 50 μm thick sensors
- Small improvement to two strip efficiency observed when decreasing metal electrode size from 100 to 50 μm
- BNL 20 μm thick sensors have small signal size
 - Adapt design, e.g. deeper gain layer, larger metal electrode, tune resistivity,...
 - Worth considering 30-40 μm thick sensors?
- **HPK 20 and 30 μm sensors reach below 25 ps time resolution**
 - Signal sharing not useful for position reconstruction
 - **Fully efficient and have uniform time resolution**
- Shown preliminary results and will continue analyzing the data

Backup

Sensors Tested

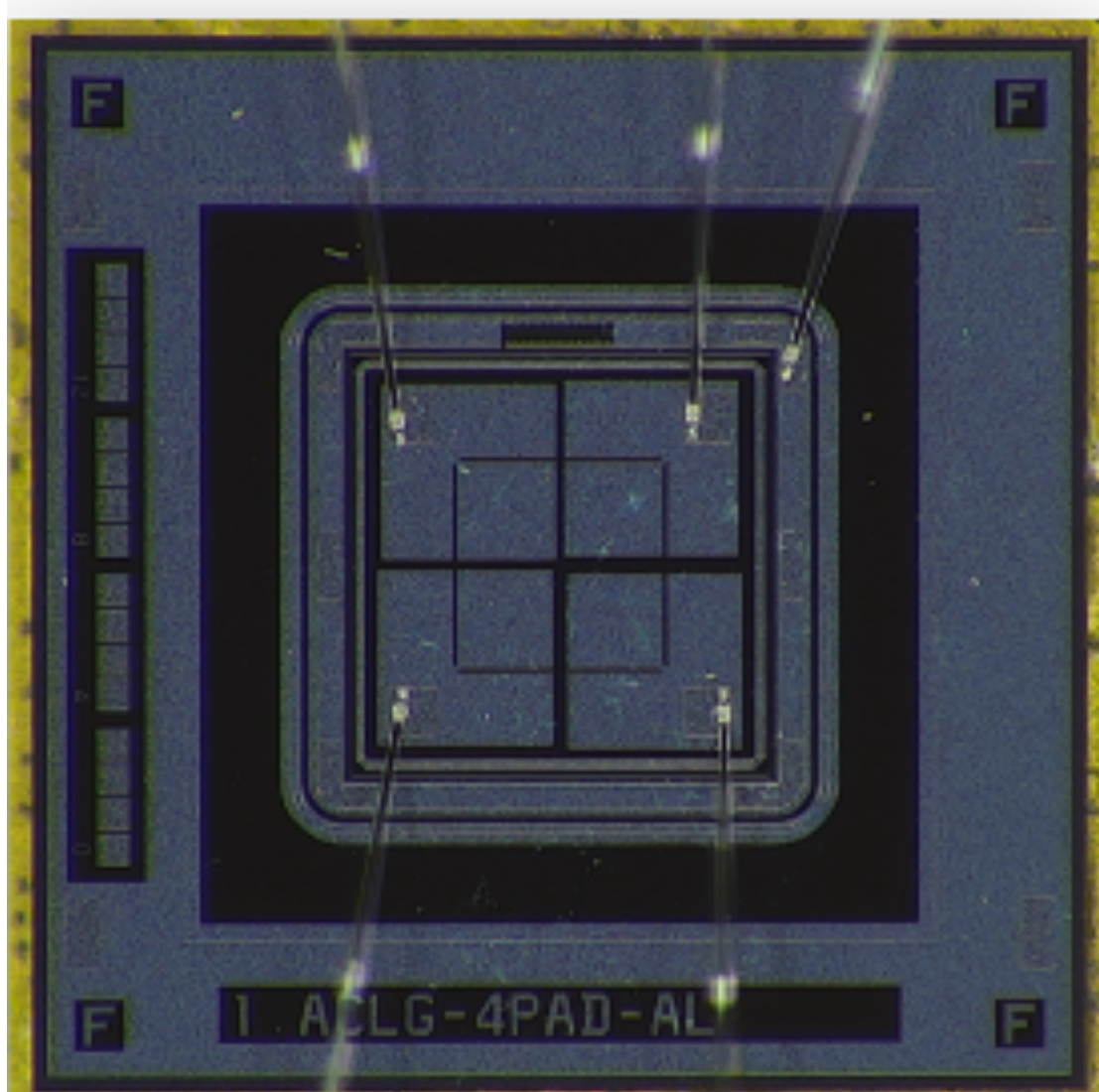
- 8 BNL sensors
 - 1 cm size, 50/100 μm width metal electrodes
 - 20 μm vs 50 μm
 - 2 wafer types
- 6 HPK 500x500 μm pad E600, 2x2 sensors
 - 20 μm (2 copies), 30 μm (2 copies) and 50 μm (2 copies) thickness
 - Copies of the same sensor tested on FNAL and UCSC boards

Thickness	Production	Channel Size	Gap	Wafer number
20 micron	BNL Strips	500 μm x 1.0 cm	400 μm	W3074
		500 μm x 1.0 cm	400 μm	W3075
		500 μm x 1.0 cm	450 μm	W3074
		500 μm x 1.0 cm	450 μm	W3075
	HPK Pixels	500x500 μm^2	20-50 μm	-
30 micron	HPK Pixels	500x500 μm^2	20-50 μm	-
50 micron	BNL Strips	500 μm x 1.0 cm	400 μm	W3051
		500 μm x 1.0 cm	450 μm	W3051
		500 μm x 1.0 cm	450 μm	W3052
		500 μm x 2.5 cm	400/450 μm mix	W3051
	HPK Pixels	500x500 μm^2	20-50 μm	-

Test beam 2021 results: HPK Pixels

- We have sensors from KEK and U. of Tsukuba that are fabricated at HPK
- Here we have a 2x2 pad sensor with 500 μm size pads
- **The overall performance we observe is great:**
 - 100% efficient, primary signal size are large (~ 128 mV), and signal sharing extends well into neighboring channel
- **Show effects of signal sharing in 2 dimensions by looking at the signal size for hits to the top left pad**

[arxiv:2201.07772](https://arxiv.org/abs/2201.07772)



HPK 2x2, 500 μm pad size

